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(54) **WAFER RECONSTITUTION AND DIE-STITCHING**

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(63) Continuation of application No. 16/503,806, filed on Jul. 5, 2019, now Pat. No. 11,158,607.

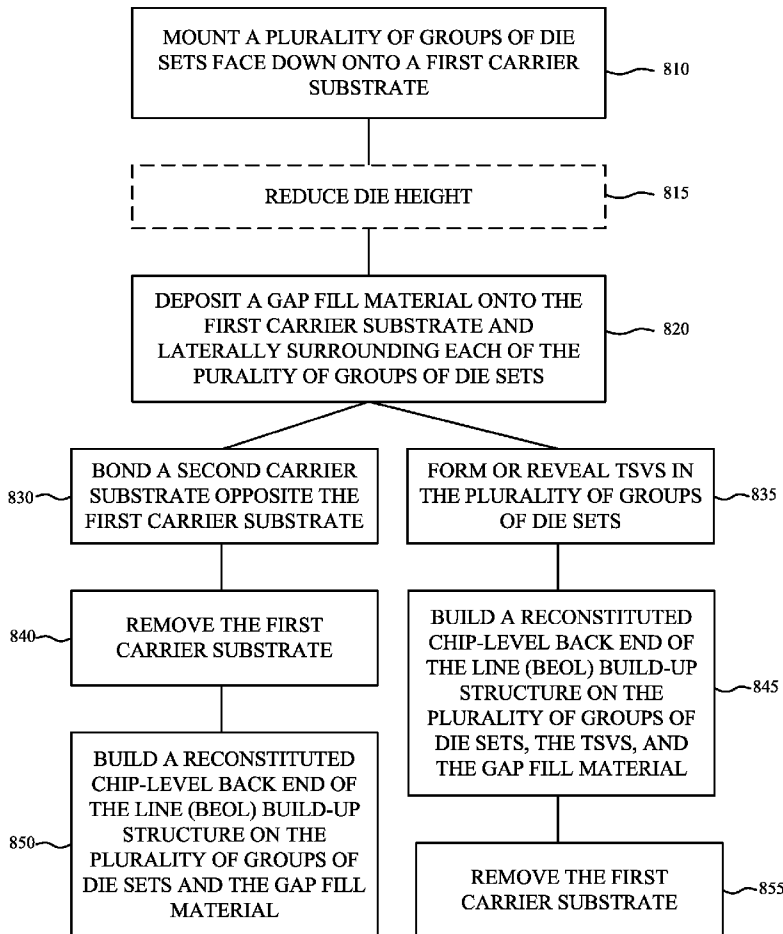
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H01L 21/56 (2006.01)

(57) **ABSTRACT**

Stitched die packaging techniques and structures are described in which reconstituted chips are formed using wafer reconstitution and die-stitching techniques. In an embodiment, a chip includes a reconstituted chip-level back end of the line (BEOL) build-up structure to connect a die set embedded in an inorganic gap fill material.



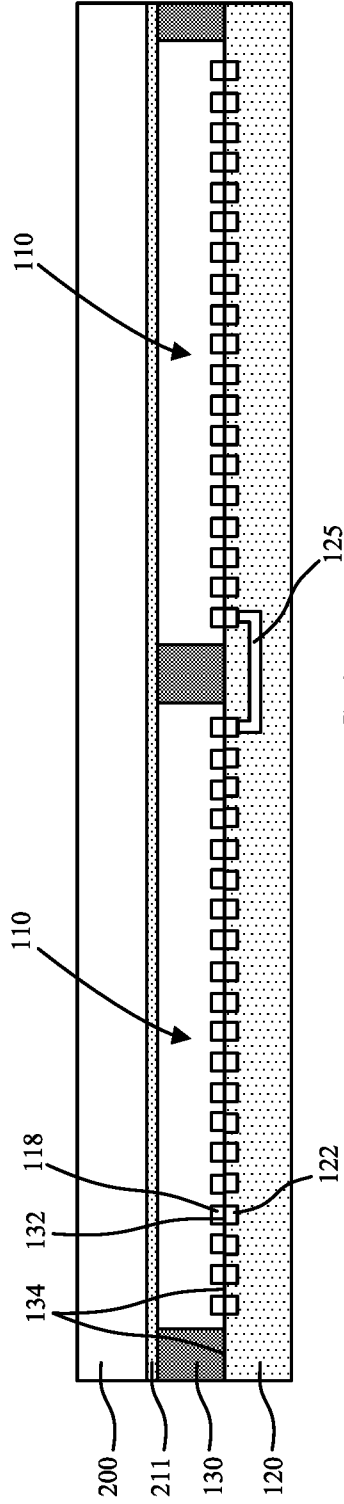


FIG. 1

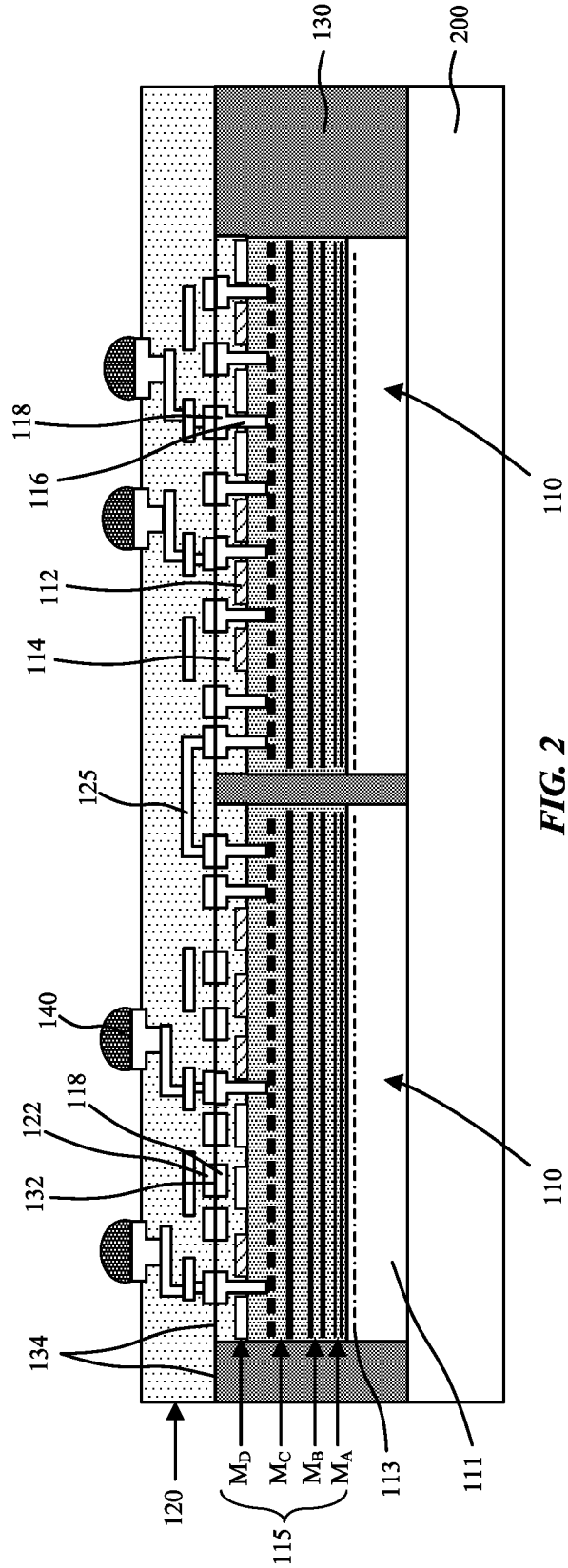


FIG. 2

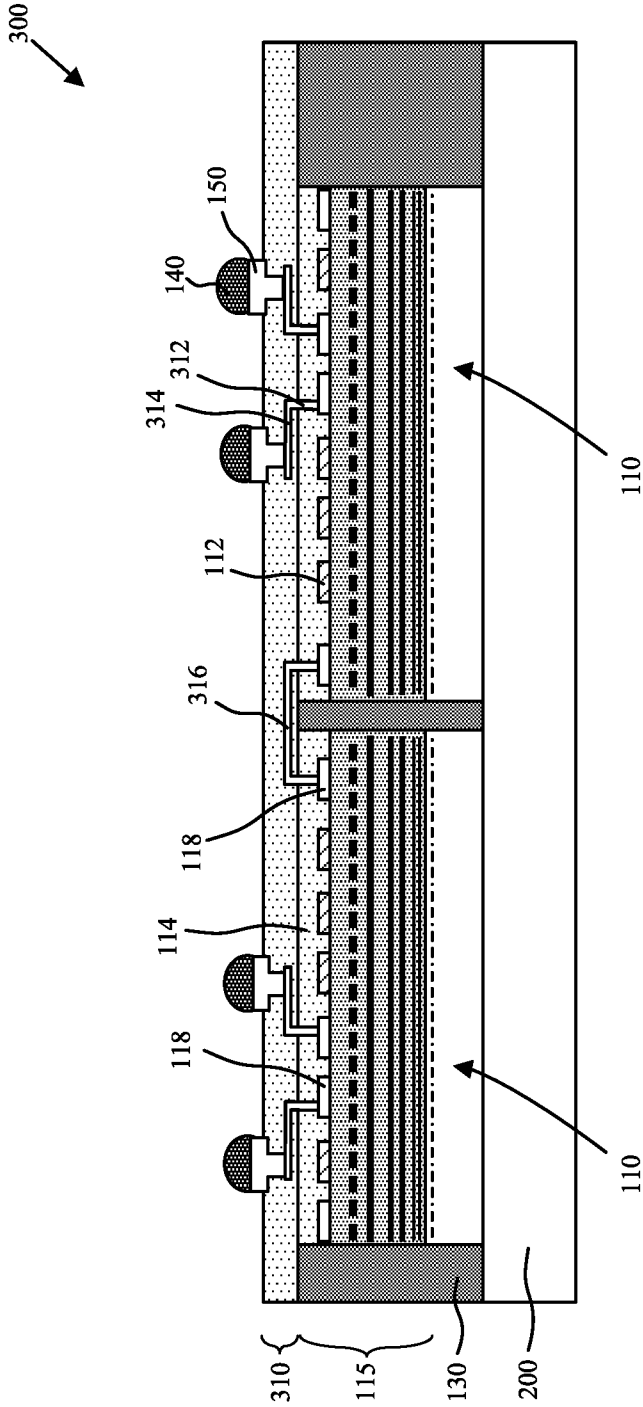


FIG. 5

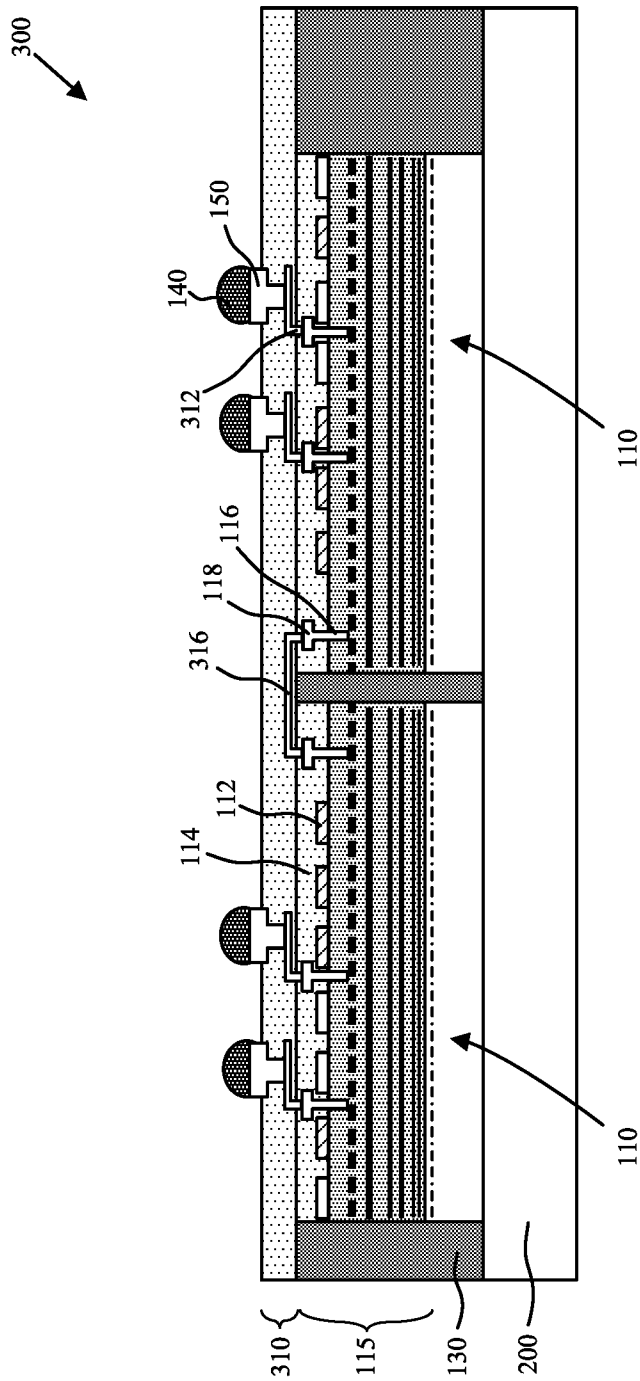


FIG. 6

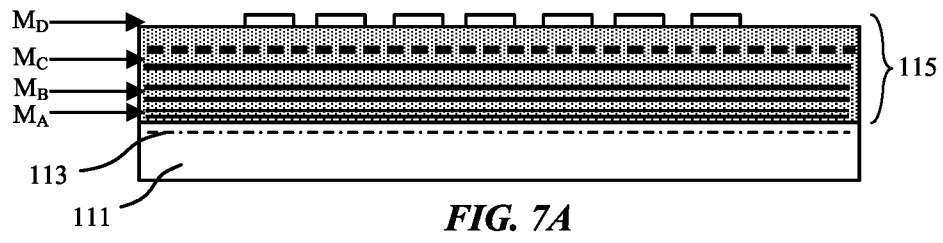


FIG. 7A

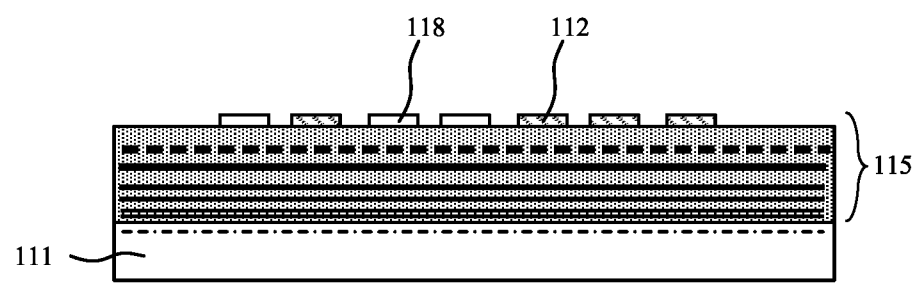


FIG. 7B

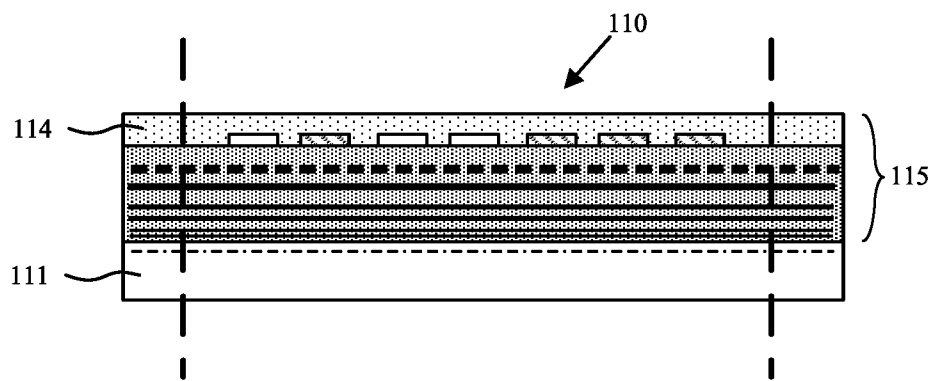


FIG. 7C

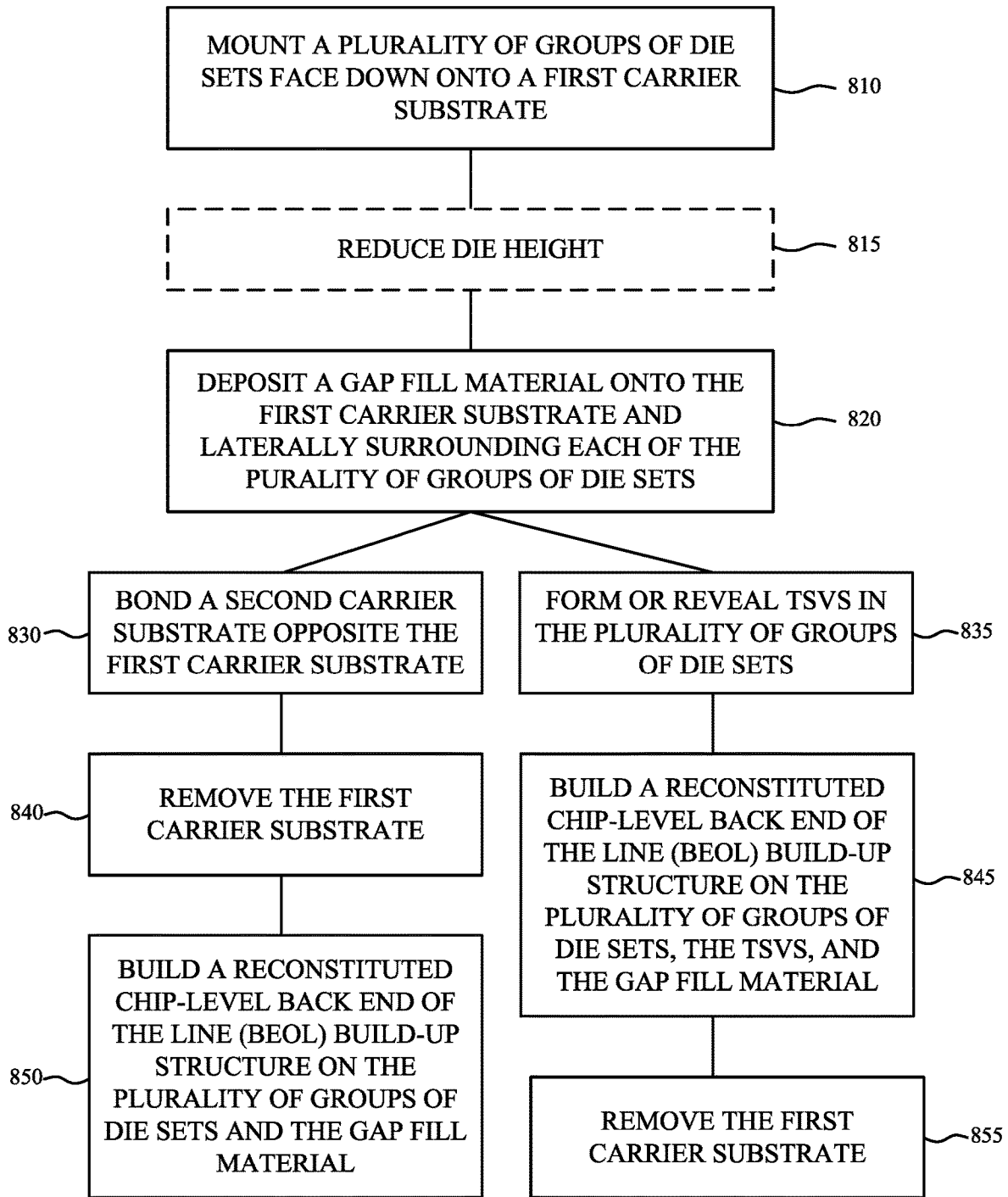


FIG. 8

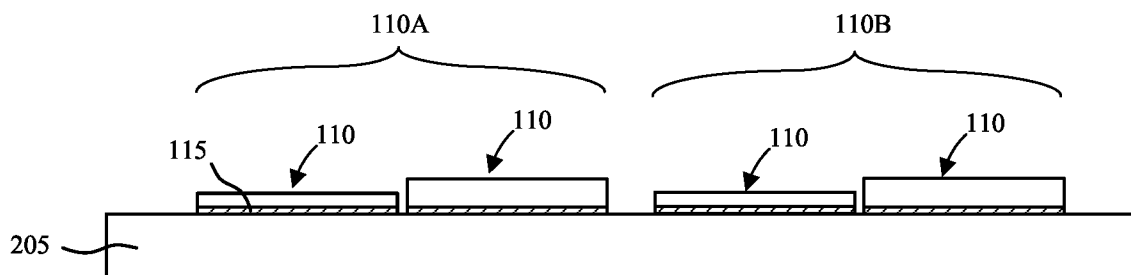


FIG. 9A

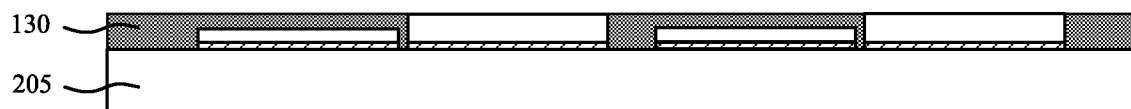


FIG. 9B



FIG. 9C

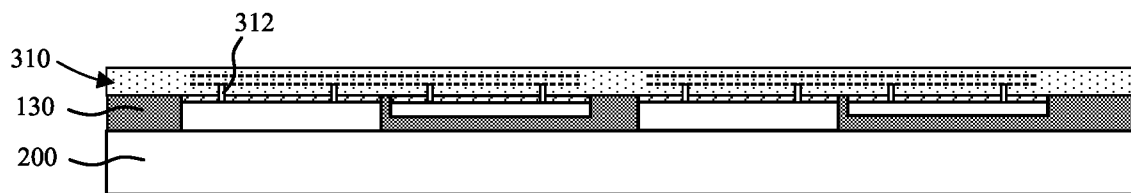


FIG. 9D

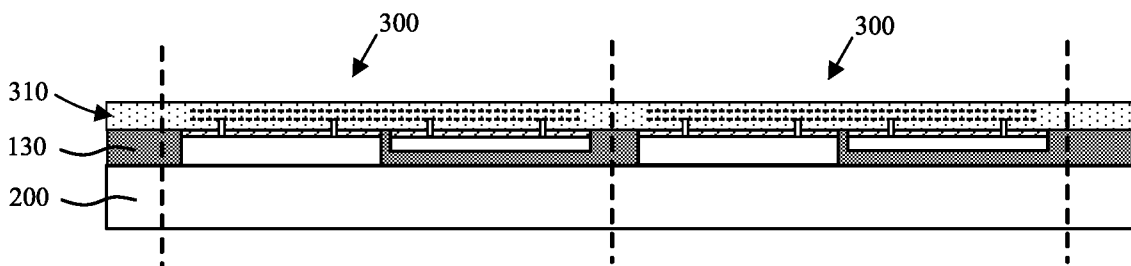


FIG. 9E

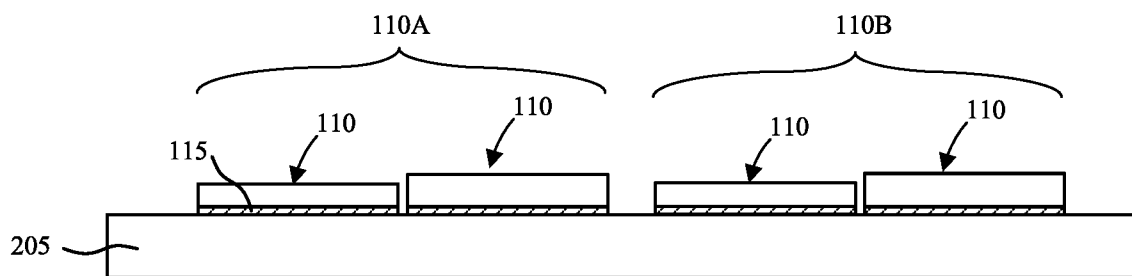


FIG. 9F

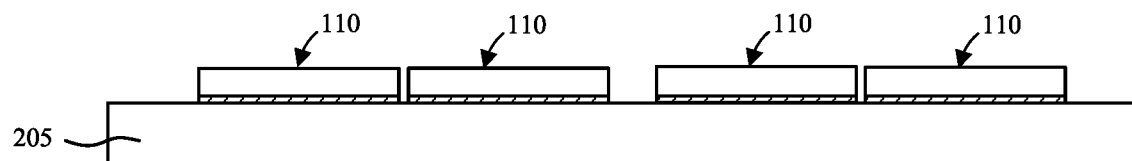


FIG. 9G

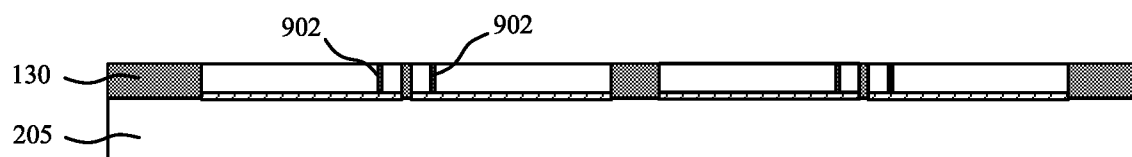


FIG. 9H

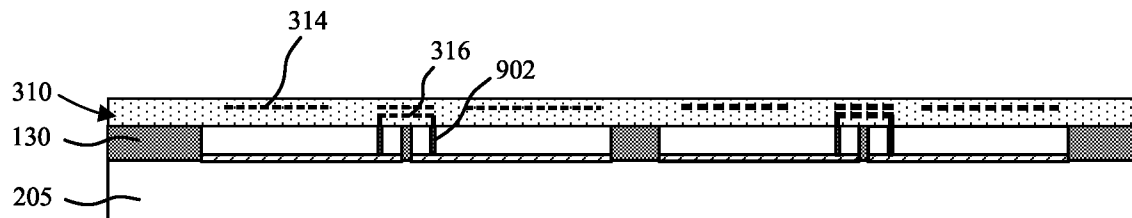


FIG. 9I

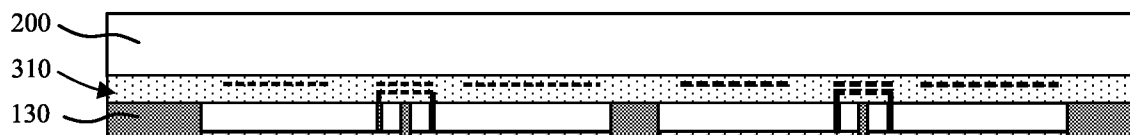


FIG. 9J

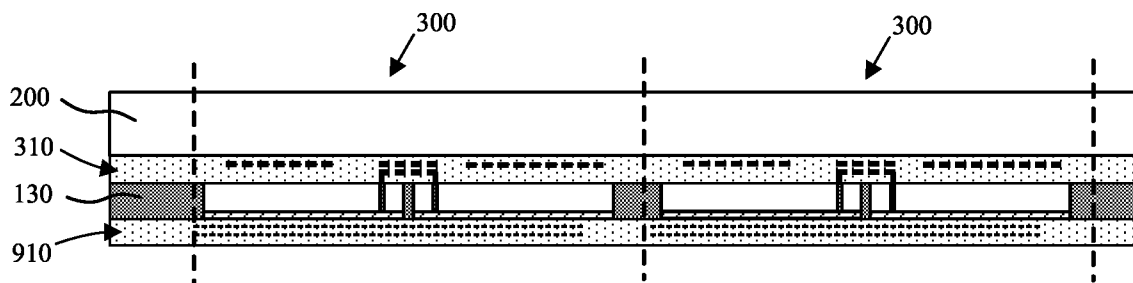
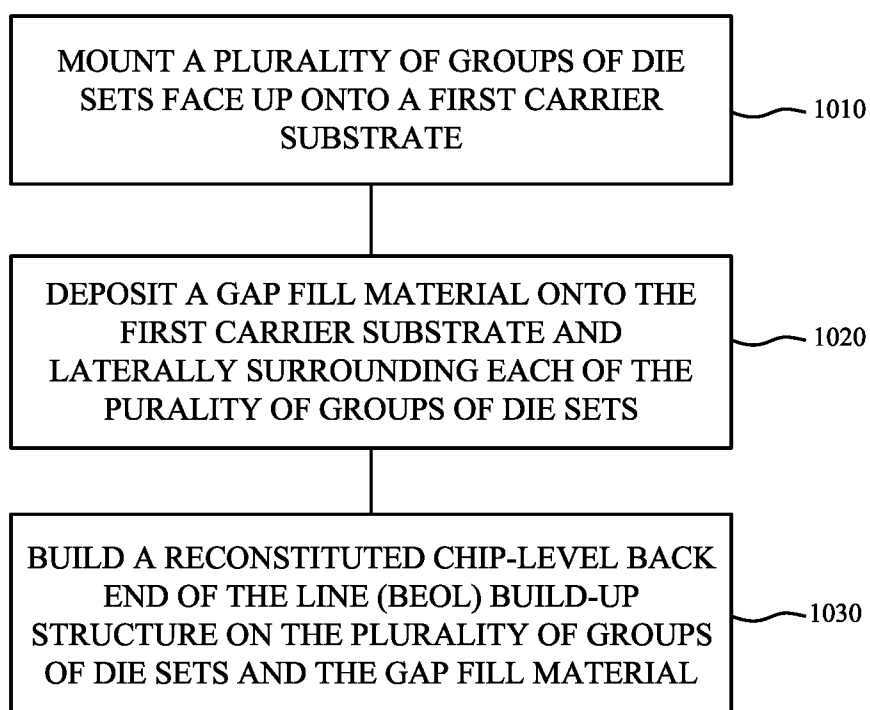


FIG. 9K

**FIG. 10**

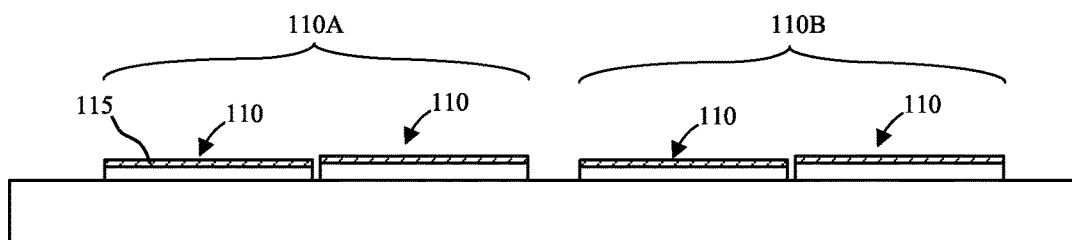


FIG. 11A

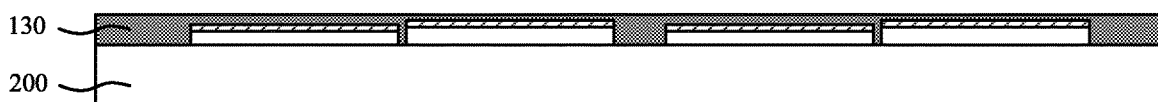


FIG. 11B

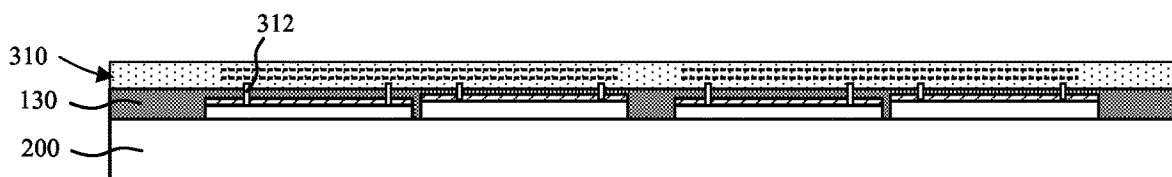


FIG. 11C

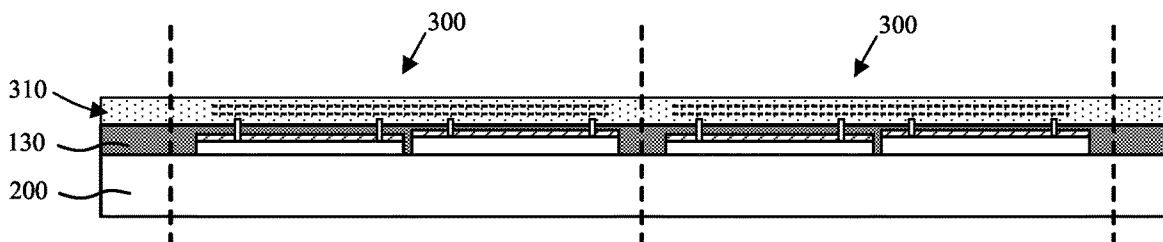


FIG. 11D

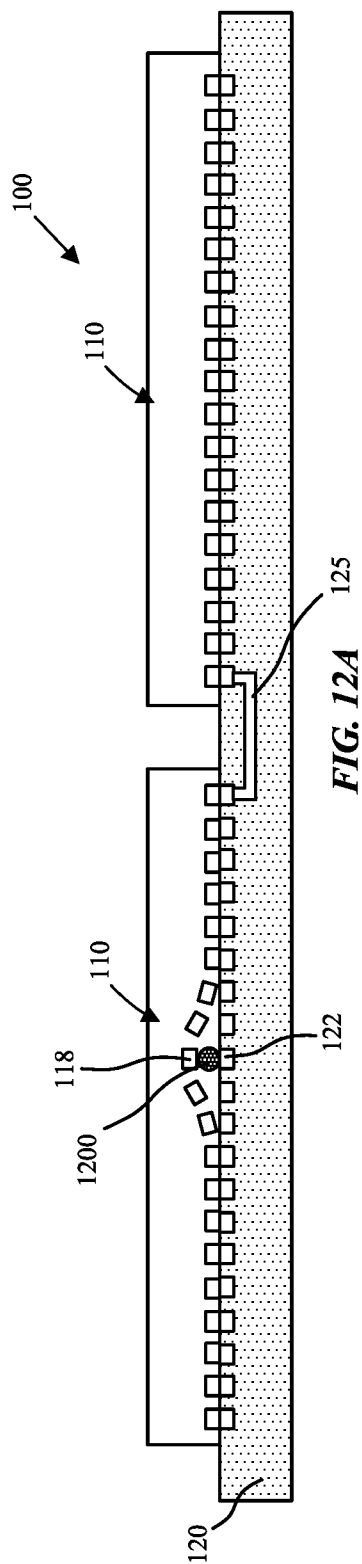


FIG. 12A

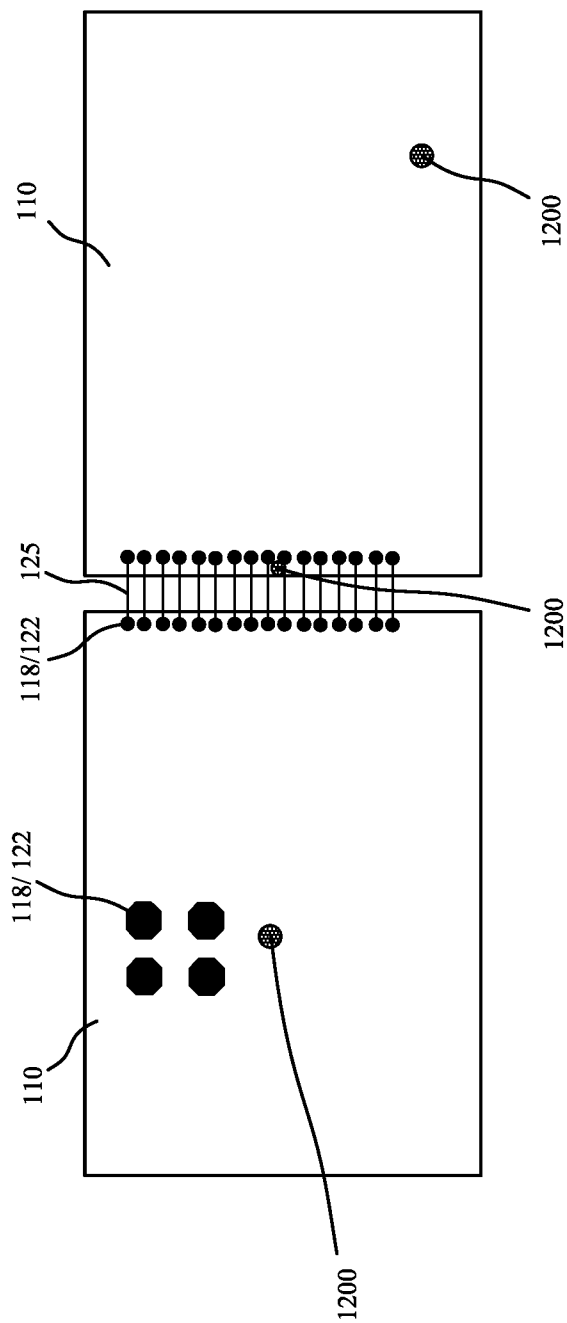


FIG. 12B

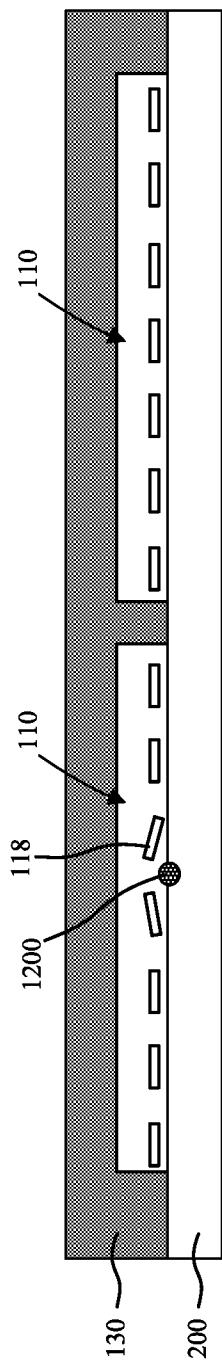


FIG. 13A

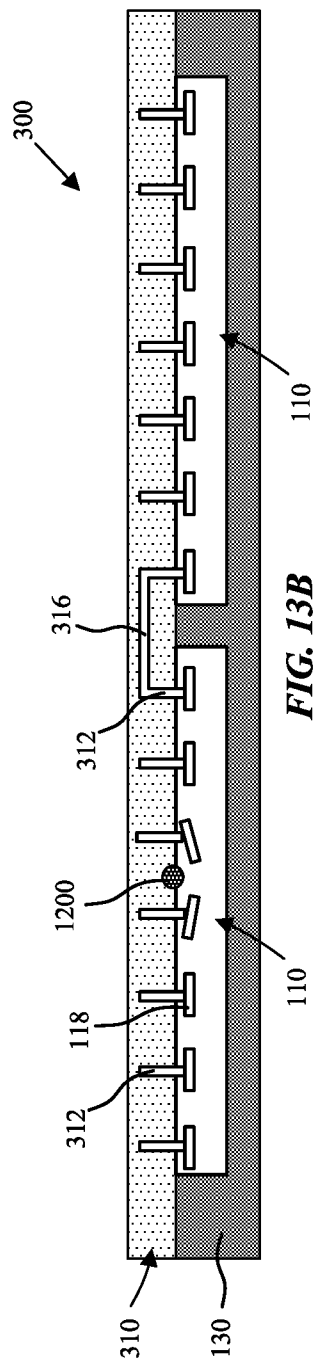


FIG. 13B

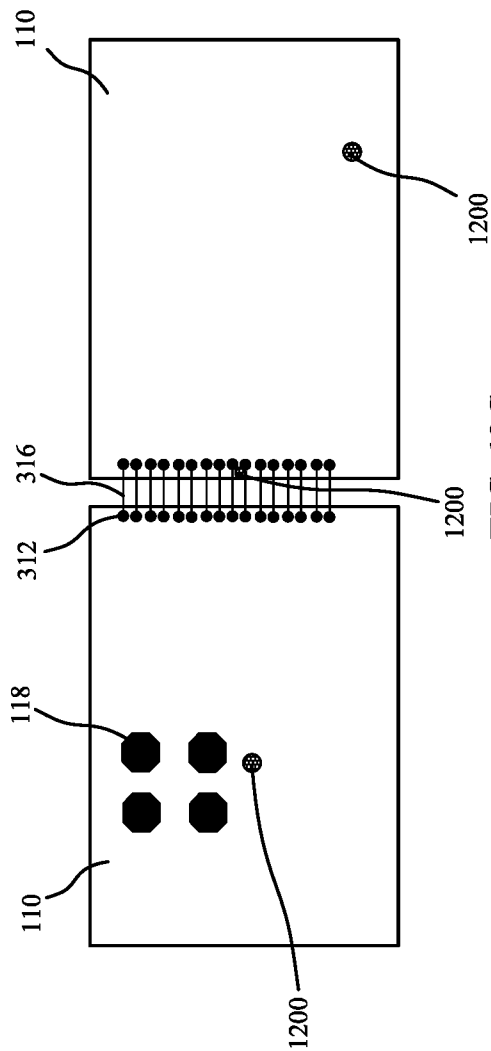


FIG. 13C

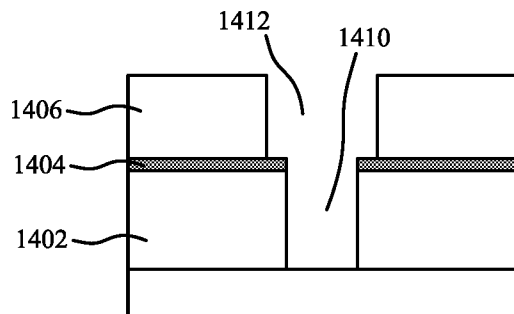


FIG. 14A

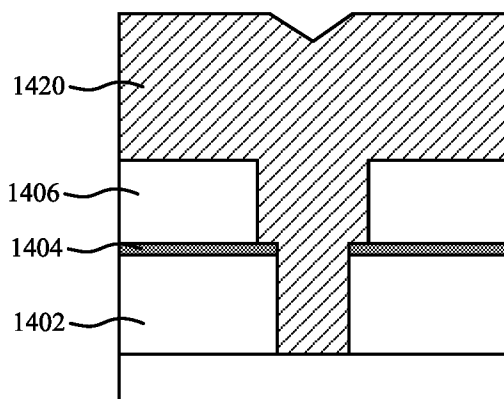


FIG. 14B

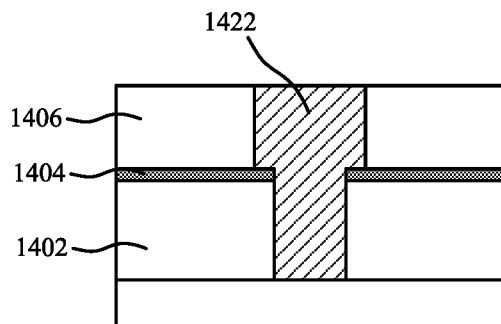


FIG. 14C

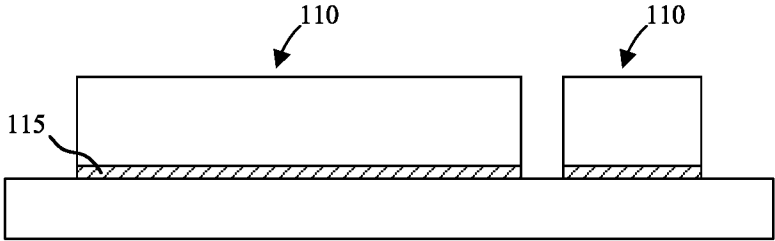


FIG. 15A

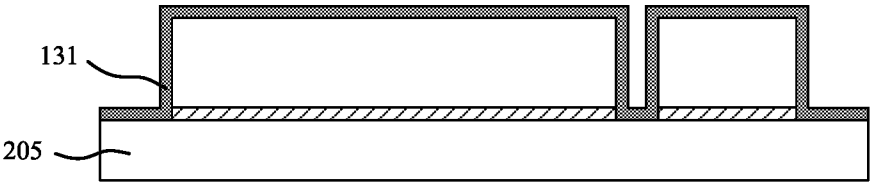


FIG. 15B

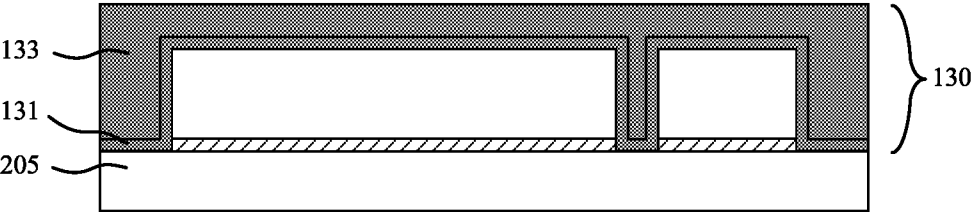


FIG. 15C

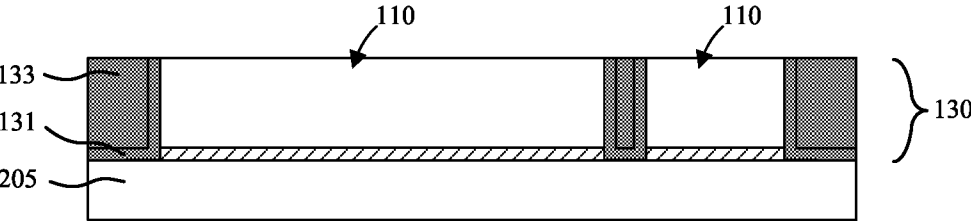


FIG. 15D

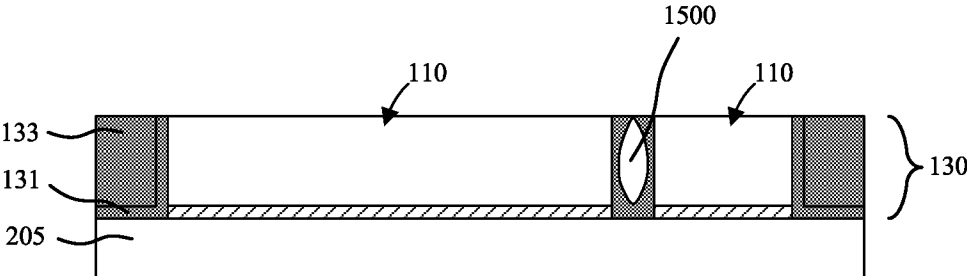


FIG. 15E

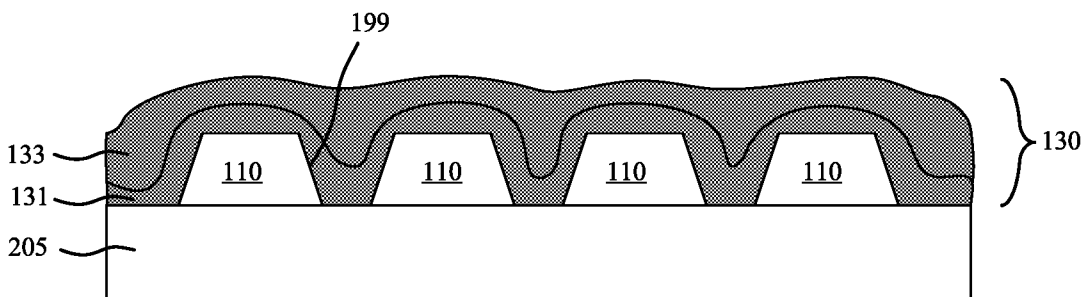


FIG. 15F

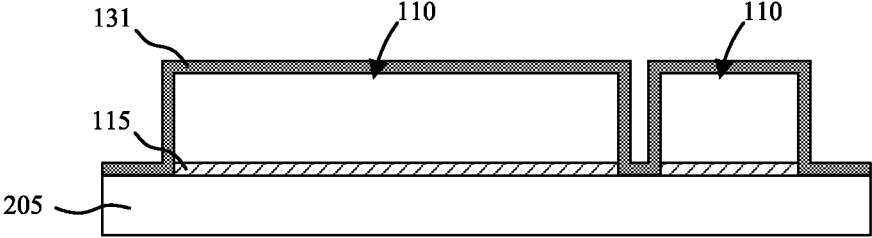


FIG. 16A

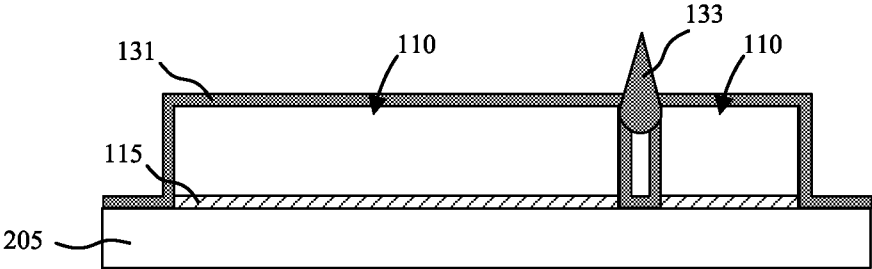


FIG. 16B

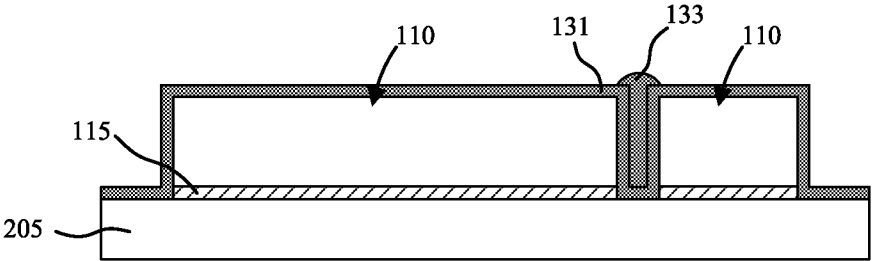


FIG. 16C

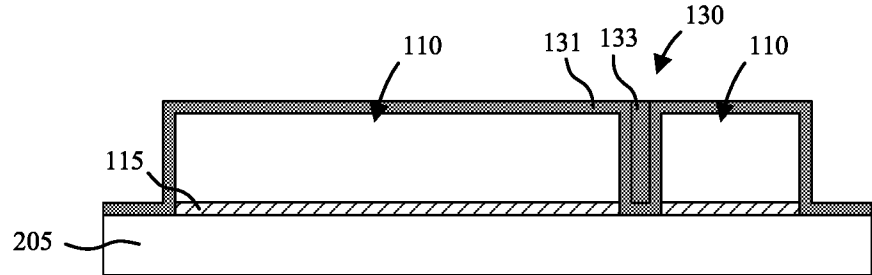


FIG. 16D

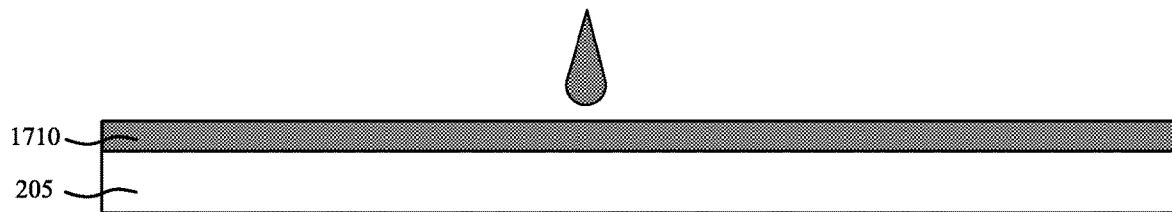


FIG. 17A

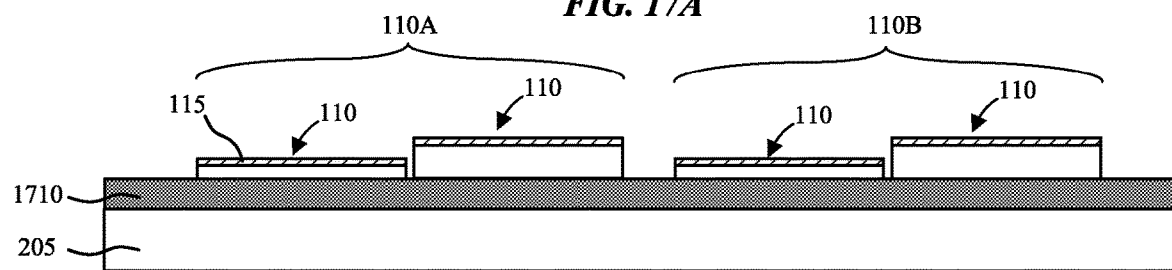


FIG. 17B

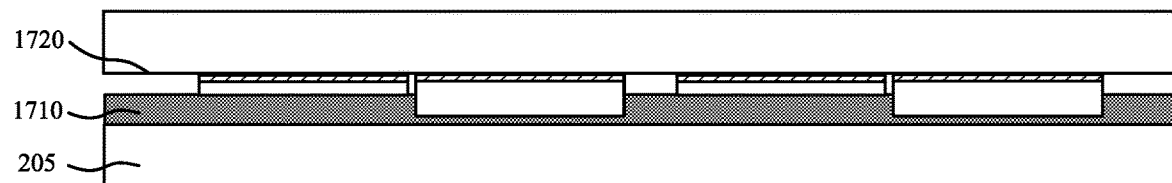


FIG. 17C

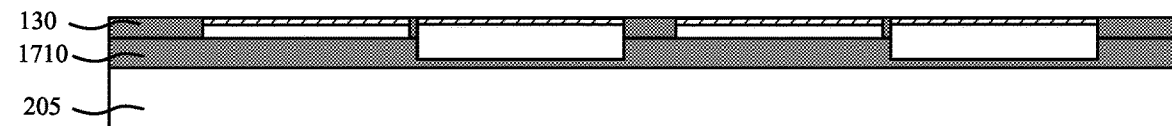


FIG. 17D

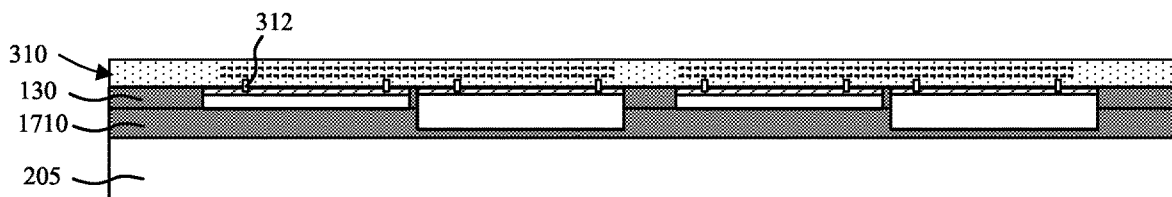


FIG. 17E

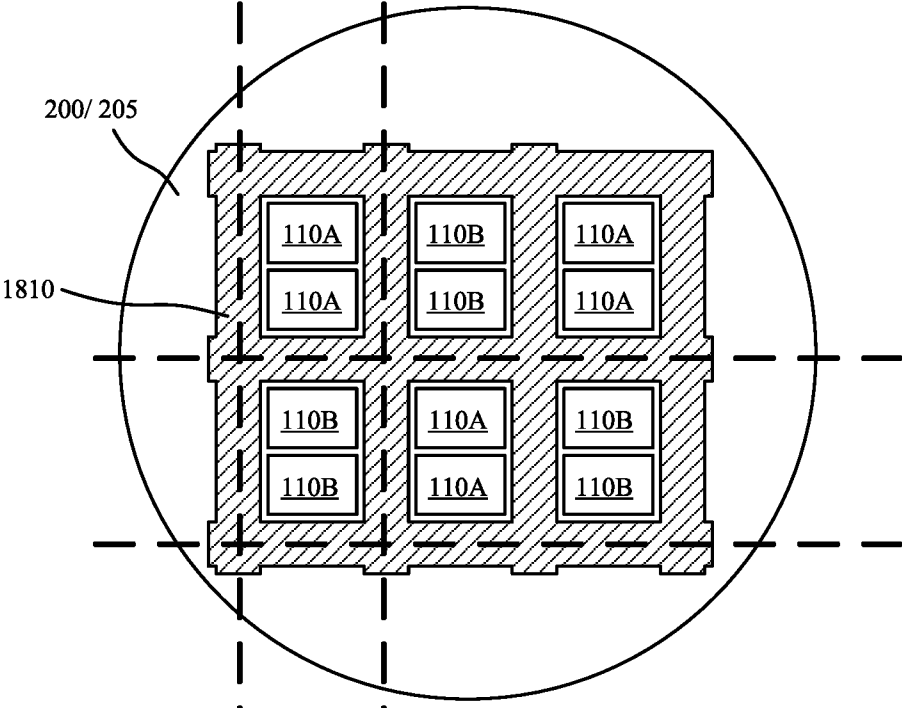


FIG. 18A

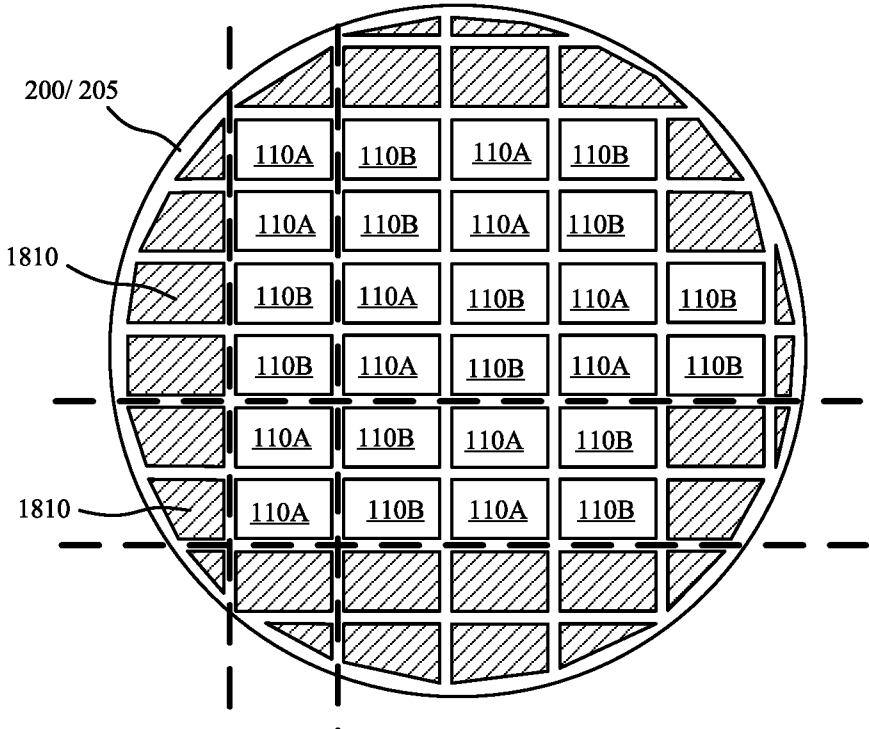


FIG. 18B

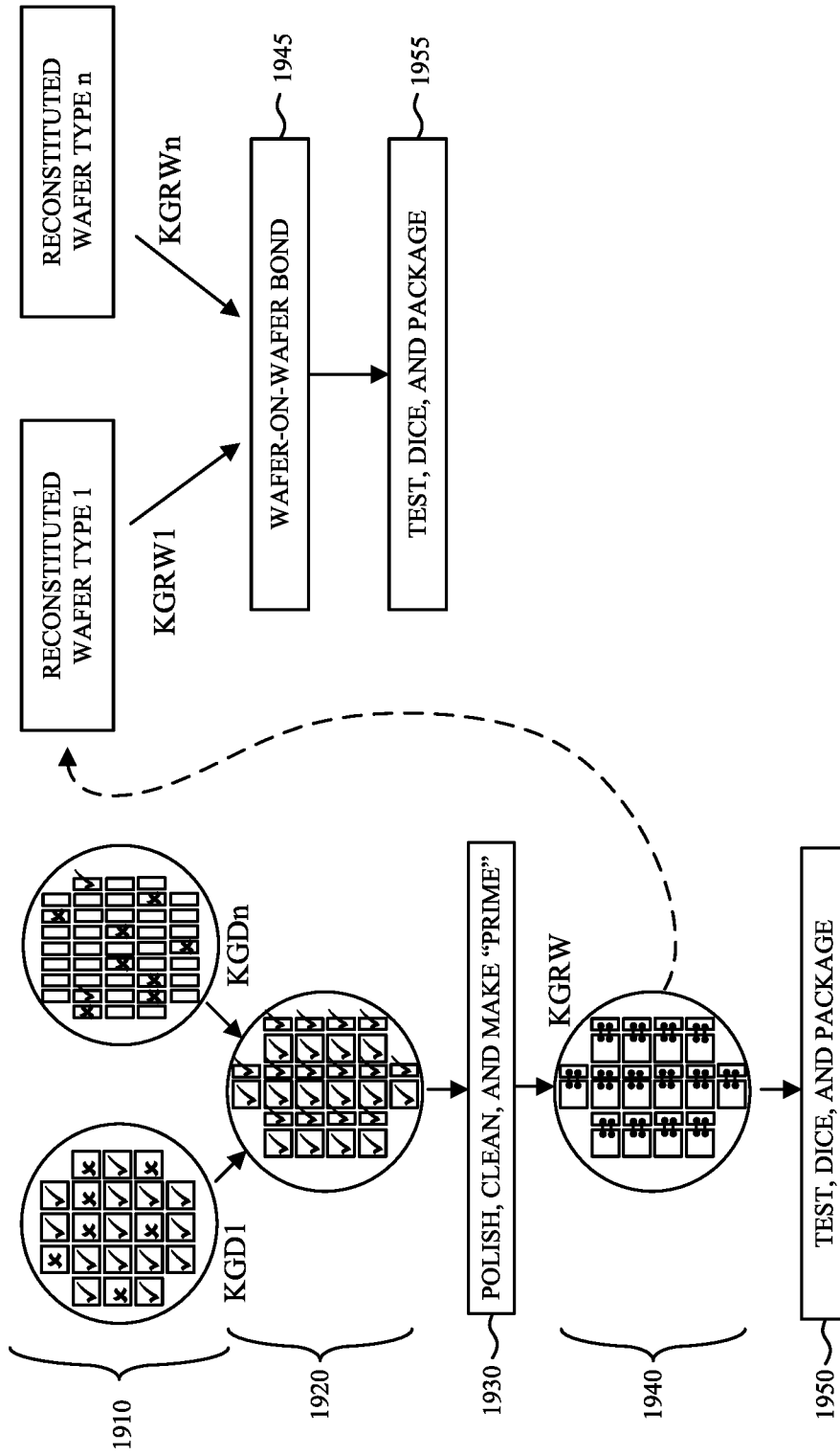


FIG. 19

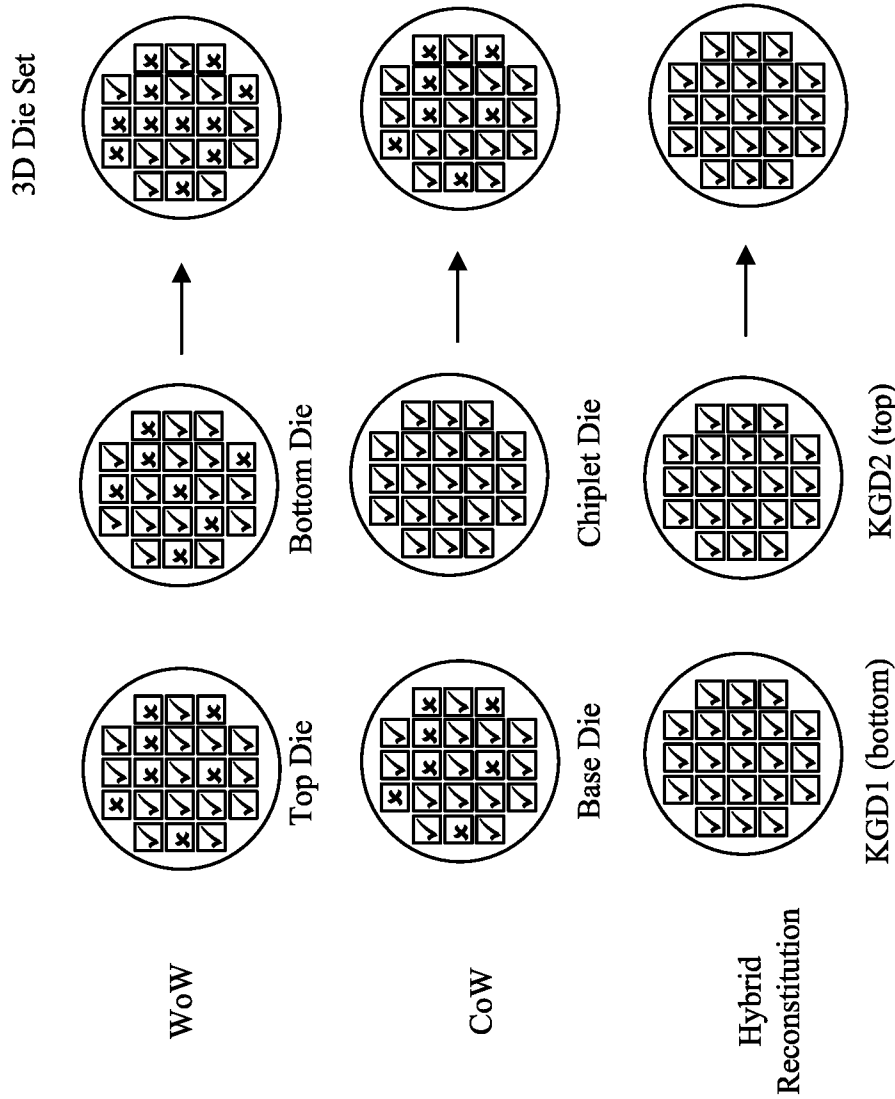


FIG. 20

WAFER RECONSTITUTION AND DIE-STITCHING

RELATED APPLICATIONS

[0001] This application is a continuation of co-pending U.S. patent application Ser. No. 16/503,806, filed Jul. 5, 2019, which claims the benefit of priority of U.S. Provisional Patent Application Ser. No. 62/773,135 filed on Nov. 29, 2018, both of which are incorporated herein by reference.

BACKGROUND

Field

[0002] Embodiments described herein relate to integrated circuit (IC) manufacture, and the interconnection of multiple dies.

Background Information

[0003] A multi-chip module (MCM) is generally an electronic assembly in which multiple dies are integrated on a substrate. Various implementations of MCMs include 2D, 2.5D and 3D packaging. Generally, 2D packaging modules include multiple dies arranged side-by-side on a package substrate. In 2.5D packaging technologies multiple dies are bonded to an interposer with microbumps. The interposer in turn is then bonded to a package substrate. The interposer may include routing to interconnect the adjacent dies. Thus, the dies in 2.5D packaging can be directly connected to the interposer, and are connected with each other through routing within the interposer. Generally, 3D packaging modules include multiple dies stacked vertically on top of each other. Thus, the dies in 3D packaging can be directly connected to each other, with the bottom die directly connected to a package substrate. The top die in a 3D package can be connected to the package substrate using a variety of configurations, including wire bonds, and through-silicon vias (TSVs) through the bottom die.

[0004] Chip on wafer (CoW) is a particular side-by-side packaging configuration which can be utilized to provide dense wiring, heterogeneous integration, and is scalable. In a particular configuration, hybrid bonding between the dies and interposer can be utilized with metal-metal and oxide-oxide bonding to achieve a high connection density by avoiding the use of solder bumps for die to interposer connections.

SUMMARY

[0005] Stitched die packaging solutions including wafer reconstitution and die-stitching techniques are described. In an embodiment a chip includes a reconstituted chip-level back end of the line (BEOL) build-up structure including a plurality of interconnects, a die set on the reconstituted chip-level BEOL build-up structure, and an inorganic gap fill material on the reconstituted chip-level BEOL build-up structure and surrounding the die set. The inorganic gap fill material may be formed of an oxide, oxynitride (e.g. SiO_xN_y), multiple oxynitride with variable ratios and thickness, or silicon matrix for example. In an embodiment, the reconstituted chip-level BEOL build-up structure includes intra-die interconnections for a first die of the die set, intra-die interconnections for a second die of the die set, and die-to-die interconnections between the first die and the

second die. The wafer reconstitution sequences may be performed with both die face-up and face-down processing sequences. In an embodiment, a method of fabricating a reconstituted wafer includes mounting a plurality of groups of die sets face down onto a first carrier substrate; depositing a gap fill material onto the first carrier substrate and laterally surrounding each die of the plurality of groups of die sets, bonding a second carrier substrate opposite the first carrier substrate, and removing the first carrier substrate. The gap fill material may include an inorganic matrix material such as an oxide or silicon, for example. A reconstituted chip-level BEOL build-up structure can then be formed on the front sides of the plurality of groups of die sets and the gap fill material. In an embodiment a back side reconstituted chip-level BEOL build-up structure is formed on exposed through silicon vias on back sides of the plurality of groups of die sets.

[0006] In an embodiment, a method of fabricating a reconstituted wafer includes mounting a plurality of groups of die sets face up onto a first carrier substrate, and depositing a gap fill material onto the first carrier substrate and laterally surrounding each die of the plurality of groups of die sets. The gap fill material may include an inorganic matrix material such as an oxide or silicon, for example. A reconstituted chip-level BEOL build-up structure can then be formed on the plurality of groups of die sets and the gap fill material.

[0007] The wafer reconstitution sequences in accordance with embodiments may be extended to 3D packing solutions, such as a wafer on wafer (or wafer to wafer) process which includes bonding a first reconstituted wafer of known good dies to a second reconstituted wafer of known good dies, followed by singulation of a plurality of 3D reconstituted chips.

BRIEF DESCRIPTION OF THE DRAWINGS

[0008] FIG. 1 is a schematic cross-sectional side view illustration of a CoW packaging technique.

[0009] FIG. 2 is a schematic cross-sectional side view illustration of a die-to-interposer CoW interface.

[0010] FIG. 3 is a schematic cross-sectional side view illustration of a chip fabricated with a wafer reconstitution and die-stitching technique in accordance with an embodiment.

[0011] FIG. 4 illustrates a back end of the line wiring for contact with inner chip layers in accordance with an embodiment.

[0012] FIG. 5 illustrates a back end of the line wiring for contact with a top metal layer in accordance with an embodiment.

[0013] FIG. 6 illustrates a back end of the line wiring for via and pad built in the original die in accordance with an embodiment.

[0014] FIGS. 7A-7C are schematic cross-sectional side view illustrations of a die-level BEOL build-up structure processing sequence in accordance with an embodiment.

[0015] FIG. 8 is a process flow diagram of an aligned front die face-down processing sequence of a wafer reconstitution and die-stitching technique in accordance with an embodiment.

[0016] FIGS. 9A-9E are schematic cross-sectional side view illustrations of the process flow illustrated in FIG. 8 with a front side reconstituted chip-level BEOL build-up structure in accordance with an embodiment.

[0017] FIGS. 9F-9K are schematic cross-sectional side view illustrations of the process flow illustrated in FIG. 8 with a back side reconstituted chip-level BEOL build-up structure in accordance with an embodiment.

[0018] FIG. 10 is a process flow diagram of an aligned front die face-up processing sequence of a wafer reconstitution and die-stitching technique in accordance with an embodiment.

[0019] FIGS. 11A-11D are schematic cross-sectional side view illustrations of the process flow illustrated in FIG. 10 in accordance with an embodiment.

[0020] FIG. 12A is a schematic cross-sectional side view illustration showing a particle during wafer reconstitution and hybrid bonding phase of a CoW process.

[0021] FIG. 12B is a schematic top view illustration showing particle sensitivity on a CoW hybrid bonding process.

[0022] FIG. 13A is a schematic cross-sectional side view illustration showing less particle sensitivity during a wafer reconstitution phase of a wafer reconstitution and die-stitching technique process in accordance with an embodiment.

[0023] FIG. 13B is a schematic cross-sectional side view illustration showing a particle during interconnection phase of a wafer reconstitution and die-stitching technique process in accordance with an embodiment.

[0024] FIG. 13C is a schematic top view illustration showing particle effect on a wafer reconstitution and die-stitching technique process in accordance with an embodiment.

[0025] FIGS. 14A-14C are schematic cross-sectional side view illustrations of an aluminum dual damascene process in accordance with an embodiment.

[0026] FIGS. 15A-15D are schematic cross-sectional side view illustrations of a gap fill deposition sequence in accordance with an embodiment.

[0027] FIG. 15E is a schematic cross-sectional side view illustration of a gap fill with air gap in accordance with an embodiment.

[0028] FIG. 15F is a schematic cross-sectional side view illustration of a gap fill material between dies with tapered sidewalls in accordance with an embodiment.

[0029] FIGS. 16A-16D are schematic cross-sectional side view illustrations of a gap fill deposition sequence including silicon ink or paste deposition in accordance with an embodiment.

[0030] FIGS. 17A-17E are schematic cross-sectional side view illustration of an aligned front die face-up processing sequence of a wafer reconstitution and die-stitching technique with mechanical leveling in accordance with an embodiment.

[0031] FIG. 18A is a schematic top view illustration of a dummy structure between die sets to maintain aspect ratios around the die sets in accordance with an embodiment.

[0032] FIG. 18B is a schematic top view illustration of a dummy structure around die sets to maintain aspect ratios around carrier substrate edges in accordance with an embodiment.

[0033] FIG. 19 is a flow chart of a wafer reconstitution flow in accordance with an embodiment.

[0034] FIG. 20 is a flow chart comparing yield considerations of wafer on wafer, chip on wafer, and a hybrid process flow of wafer reconstitution and die-stitching technique in accordance with an embodiment.

DETAILED DESCRIPTION

[0035] Embodiments describe a 2.5D packaging solution in which a chip may include a reconstituted chip-level back end of the line (BEOL) build-up structure including a plurality of interconnects, a die set on the reconstituted chip-level BEOL build-up structure, and an inorganic gap fill material on the reconstituted chip-level BEOL build-up structure and surrounding the die set.

[0036] Some aspects of embodiments may include wafer reconstitution with back end of the line (BEOL) interconnections to form side-by-side (SBS) heterogeneous interconnections. Reconstitution using inorganic materials (e.g. oxide, silicon) may allow for higher temperature process, as well as finer feature sets. The reconstituted wafers can be known good reconstituted wafers (KGRW) for wafer on wafer (WoW) processes, thereby improving yield.

[0037] In some aspects, reconstituted chip-level BEOL interconnections can form (inter) die-to-die (D2D) interconnects, as well as (intra) on-chip interconnect (supporting). The reconstituted chip-level BEOL interconnections may include aluminum damascene interconnects in some embodiments. For example, these may be single damascene (two steps) or dual damascene using electro-deposition, for example. The particular configurations of the die (active side up) with inorganic dielectric in the reconstituted chip-level BEOL build-up structure can enable standard via and interconnect process path.

[0038] In some aspects, the packaging scheme can minimize or remove altogether electrostatic discharge (ESD) protection on the dies (therefore closer to on-chip like bus). This can reduce capacitance and area.

[0039] In various embodiments, description is made with reference to figures. However, certain embodiments may be practiced without one or more of these specific details, or in combination with other known methods and configurations. In the following description, numerous specific details are set forth, such as specific configurations, dimensions and processes, etc., in order to provide a thorough understanding of the embodiments. In other instances, well-known semiconductor processes and manufacturing techniques have not been described in particular detail in order to not unnecessarily obscure the embodiments. Reference throughout this specification to “one embodiment” means that a particular feature, structure, configuration, or characteristic described in connection with the embodiment is included in at least one embodiment. Thus, the appearances of the phrase “in one embodiment” in various places throughout this specification are not necessarily referring to the same embodiment. Furthermore, the particular features, structures, configurations, or characteristics may be combined in any suitable manner in one or more embodiments.

[0040] The terms “above”, “over”, “to”, “spanning” and “on” as used herein may refer to a relative position of one layer with respect to other layers. One layer “above”, “over”, “spanning” or “on” another layer or bonded “to” or in “contact” with another layer may be directly in contact with the other layer or may have one or more intervening layers. One layer between layers may be directly in contact with the layers or may have one or more intervening layers.

[0041] In one aspect, embodiments describe stitched-die chip structures that can realize the benefits of both CoW and BEOL interconnection techniques while avoiding many of the associated potential drawbacks. For example, several CoW beneficial properties include being heterogeneous (uses

different substrates), dense I/O per unit area, dense wiring per mm, scalability, being repartition and reintegration friendly, and providing die placement accuracy. Some potential drawbacks of CoW include expense of integrating a hybrid bonding fabrication line into a facility, maturity of the technology, particle sensitivity (especially during test, dicing), and high temperature for hybrid bonding.

[0042] BEOL interconnection technology beneficial properties include being a mature process (which affects yield and expense), providing dense I/O per unit area, dense wiring per mm, scalability, being less particle sensitive compared to CoW (especially during test, dicing), and use of moderate temperatures. Some potential drawbacks include being homogeneous (same substrate), and repartition and reintegration can be harder (e.g. due to fixed placement, reticle cost to reconfigure, etc.).

[0043] The stitched die packaging techniques in accordance with embodiments may get the best of both CoW and BEOL options. For example, embodiments may draw heterogeneity from CoW with the reconstituted wafer. Additionally, embodiments may draw dense IO, die placement accuracy, and the repartition and reintegration friendliness from CoW. Embodiments may also draw beneficial properties from BEOL including process maturity, dense IO, dense wiring, scalability, less particle sensitivity, and moderate temperatures.

[0044] Referring now to FIG. 1 a cross-sectional side view illustration is provided of CoW packaging technique in which side-by-side (SBS) dies **110** are hybrid bonded to an interposer **120**, and secured with an oxide gap fill **130**. As shown, metal-metal bonds **132** can be made between the die pads **118** and interposer pads **122**. Additionally, oxide-oxide bonds **134** may be formed between the dies and interposer, as well as the oxide gap fill and interposer. It has been observed that such a CoW technique may incite costs due to being very sensitive to particulates, and need to maintain strict environmental control during hybrid bonding. Additionally, hybrid bonding lines can be a major non-recurring expense. Another drawback is that the oxide gap fill **130** has a thermal expansion CTE mismatch with silicon. Also forming the oxide gap fill is slow and costly. This can also impose restrictions of a thin die **110** (e.g. less than 20 microns) and substrate size. See for example, the schematic cross-sectional side view illustration of a die-to-interposer CoW interface in FIG. 2 which shows the dies **110** after hybrid bonding to interposer **120** and bump **140** placement, and prior to removal of carrier substrate **200**. FIG. 2 additionally illustrates die-level BEOL build-up structure **115** routing, which can include one or more metal and dielectric layers, formed over the active devices **113** formed in a semiconductor substrate **111**. Each die **110** includes both the semiconductor substrate **111** and a die-level BEOL build-up structure **115**. Die-level BEOL build-up structure **115** may be formed using traditional BEOL processing techniques, such as damascene, etc. Die-level BEOL build-up structure **115** may include wiring layers such as lower wiring layer $M_{A,}$ middle wiring layers $M_{B,}$ $M_{C,}$ and upper wiring layers $M_{D,}$. As illustrated, the wiring layers may optionally have different thicknesses, with $M_{D,}$ being the thickest, and $M_{A,}$ being the thinnest (and finest, e.g. width). Additionally, die **110** preparation after testing (e.g. testing of the Al test pad **112**) can be a major recurring cost factor for CoW. Furthermore, as shown in FIG. 2, the die **110** preparation after test includes building an extra oxide **114** and copper via **116**

(minimum height required for bonding) and then a metal pad **118** before bonding to interposer **120**.

[0045] The packaging solutions including wafer reconstitution and die-stitching technique in accordance with embodiments may keep the best features of CoW and BEOL. This can be accomplished using an oxide and integrating matrix to reconstitute a good high yielding wafer (known good reconstituted wafer (KGRW)). This supports accurate alignment, heterogeneous die integration, and die partitioning. BEOL interconnects can be used to connect the die with a very high I/O area density (e.g. 5-10 μm pitch). A suitable number of coarser pitch metallization layers, or even final metallization layer can be used to provide high wiring density. Additionally, no hybrid bonding is required, which can lower associated costs and improve yield. This can further lower risk and development time. Die peripheral yield loss may be managed by feature size to particle size ratio. The reconstitution sequence may be less sensitive to die (center) area yield loss.

[0046] The reconstituted chips fabricated with a wafer reconstitution and die-stitching techniques in accordance with embodiments may achieve on-chip like wire (or very close) densities (a design collateral). Wires can have improved T-line performance and can be used for spanning longer distance. Wiring can additionally be good for clock distribution, particularly for larger spans. With the high density wiring, the number of layers can be tuned. Wires are also available to regular on-chip circuits (e.g. can route on-chip buses). Repeaters can be formed in the active silicon. There are also test considerations for the wiring, such as a portion of the bus can be provided in the die (before integration). This enables test. Then, the full buses can be routed on top to provide full functionality and bandwidth. Overall, implementation of the BEOL wiring can provide the look and feel and usage closer to on-chip environment.

[0047] The reconstituted chips fabricated with a wafer reconstitution and die-stitching techniques in accordance with embodiments may also minimize (or eliminate electrostatic discharge (ESD) circuits) in the die-to-die connections requiring less area, and reducing parasitic capacitance. ESD may still be provided in the reconstituted chip-level BEOL wiring for the chip external pads.

[0048] FIG. 3 is a schematic cross-sectional side view illustration of a chip **300** fabricated with a wafer reconstitution and die-stitching technique in accordance with an embodiment. As illustrated, the chip **300** includes a plurality of side-by-side dies **110**, which can be partitioned system on chip dies, heterogenous dies from different wafers, and from different process nodes, etc. The die **110** sets are encapsulated in a gap fill **130** material, which may be an oxide (e.g. silicon oxide) or silicon, for example. A reconstituted chip-level BEOL build-up structure **310** is formed over the dies **110** and gap fill **130**, the chip-level BEOL build-up structure **310** including vias **312**, on-chip (intra-chip) wiring **314**, and die-to-die (D2D) interconnect (wiring) **316** between the dies **110** and one or more dielectric layers **318**. The reconstituted chip-level BEOL build-up structure **310** in some embodiments may include final metallization layer and/or coarser pitch metallization layers, for example. In an embodiment, the metallization layers may be thicker layers, for example equivalent thickness or thicker than the upper wiring layers (e.g. $M_{D,}$) for the die-level BEOL build-up structures **115**.

Traditional damascene or dual damascene via connections between wiring layers may be utilized in accordance with some embodiments.

[0049] In accordance with embodiments, the reconstituted chip-level BEOL build-up structure **310** wiring makes electrical connection to the die-level build-up structures **115** for the dies **110**. This may be accomplished with Cu—Cu wiring, Al—Al wiring, and combinations of Cu—Al wiring processes. In an embodiment, die-level BEOL build-up structures **115** can include primarily Cu wiring, with an upper wiring layer (e.g. M_D) including test pads being formed of Al. In an embodiment, the reconstituted chip-level BEOL build-up structure **310** wiring includes equivalent or thicker wiring layers (though finer wiring is possible) than the upper wiring layer (e.g. M_D) of the die-level build-up structures **115**, or a wiring layer to which contact is made (e.g. M_C). The reconstituted chip-level BEOL build-up structure **310** can be formed using either Cu or Al wiring processes. In an embodiment, the reconstituted chip-level BEOL build-up structure **310** uses an Al wiring process, which may optionally use (single) damascene vias **312**. Vias **312** used to contact the die-level BEOL build-up structures **115** though may also be formed of Cu in accordance with embodiments. In some embodiments, the quality of service can be used to organize metal usage based on requirements such as latency, power, etc.

[0050] Exemplary methods of forming an oxide gap fill include chemical vapor deposition (CVD), plasma enhanced CVD (PECVD), sub-atmospheric CVD (SA-CVD) and selective oxide deposition (SELOX). Such oxide deposition techniques are epitaxial techniques commonly performed at high temperatures, are comparatively slow, and comparatively expensive. Exemplary methods for forming a silicon gap fill include epitaxial techniques such as CVD, PECVD, low pressure CVD (LPCVD), and hot wire CVD, as well as sputtering, silicon ink, silicon paste, and electro-deposition. However, epitaxial techniques such as PECVD and LPCVD may be performed at lower temperatures, while hot wire CVD may have significantly higher deposition rates. Electro-deposition may be performed using ionic liquids at low temperatures. Additionally, silicon inks and pastes may be deposited at low temperatures followed by reflows at low temperatures due to depressed melting point of silicon nanoparticles. Notably, available techniques for the formation of silicon gap fill may be performed at lower temperatures, with shorter deposition times, and potentially less expensive equipment. This can affect both throughput and cost. Where a silicon material is used to provide a gap fill **130** material and integrating matrix, the silicon gap fill **130** material can be mechanically clean (i.e. good CTE match). The silicon gap fill **130** material can also allow for inclusion of thicker (active) die **110** (e.g. 50 μm thick) compared to an oxide gap fill **130** material, that may be restricted to less than 20 μm height. Furthermore, a silicon gap fill material may allow for use of larger carrier substrate **200** options (like 200 mm, 300 mm wafers or 500x500 mm panels or larger) during fabrication. Silicon may also be lower cost (e.g. silicon can be electro-deposited, sputtered, deposited with low temperature chemical vapor deposition, or with inks or paste, for example), and can be done at low temperatures (e.g. less than 250° C., with less than 120° C. potentially feasible). With the silicon option, wafers can be made “prime” after cleaning. Silicon processing can also reintroduce the process to a mature clean fab (e.g. a mature

larger generation fab such as 90 nm or 180 nm process node, which can reduce non-recurring expenses).

[0051] Utilizing a silicon material for the gap fill in accordance with embodiments may both allow for thicker die **110** options (improved heat spreading for hot spots) and improve thermal contact with the die **110** (e.g. silicon) to gap fill **130** (silicon). Referring briefly again to FIG. 1 such a comparison for a CoW thin oxide gap fill **130** is illustrated. As shown, in a CoW implementation, the dies **110** may need to be less than 20 μm thick. Otherwise, the oxide gap fill **130** may crack due to stress. An oxide attach film **211** (between the dies **110** and the mechanical handling silicon substrate **200**) may be additionally included, though this is very thin, and provides only a small increase in thermal resistance.

[0052] Notably, the silicon gap fill is independent of wiring. Silicon gap filled reconstituted wafers could also be used for CoW/hybrid bonding processes.

[0053] Referring now to FIG. 3, a silicon gap fill **130** material can more feasibly be made thicker than an oxide gap fill material, and may be formed over the dies **110**, and may also allow for thicker dies **110**. Irrespective of the gap fill **130** material selections, the dies **110** may have at least some partial metal wiring. For example, this may include at least traditional fine pitch BEOL wiring (e.g. M_A). For example, these may include 12-18 metal layers in current technologies and possibly more in the future. These wires can include fine wiring (e.g. M_A) near the active devices **113** (transistors), and then going to BOEL like (e.g. M_B , M_C , M_D) with 0.4 to 0.8 μm pitch. Each die **110** may include sufficient wiring, and test pads **112** (e.g. aluminum pads, similar to FIG. 2) for circuit testing to identify good known dies. The wiring need not be complete, or circuits need not be complete, beyond testing requirements. Final connections may be made in the reconstituted chip-level BEOL build-up structure **310**.

[0054] The reconstituted chip-level BEOL build-up structure (inclusive of the dielectric (oxide) layer **318** illustrated) can include similar or coarser wiring than within the die wiring. For example, the intra-chip wiring **314** in the reconstituted chip-level BEOL build-up structure **310** may include a tight I/O pitch of 2-10 μm , defined by process, with no ESD protection. The die-to-die (D2D) interconnect (wiring) **316** may include similar pitch, with minimal or no ESD protection. The external chip pads **150** (e.g. may be aluminum) may have even looser I/O pitch, such as 60-130 μm , defined by flip chip bump pitch considerations.

[0055] FIG. 4 illustrates a back end of the line wiring sequence during fabrication of reconstituted chip-level BEOL build-up structure **310** for contact with inner chip layers in accordance with embodiments. As shown, the reconstituted chip-level BEOL build-up structure can include one or a plurality of metal interconnect layers and may include damascene connections. Additionally, deep vias **312** may be formed through the die-level BEOL layers to contact die metallization. This may avoid the top metal layer (e.g. M_D) including the test pads **112**. Accordingly, via **312** connections may be etched and formed into the die-level BEOL build-up structure **115** layers to connect with the die-level BEOL layers, while bypassing the testing pads **112**. Additionally, metal layers in the reconstituted chip-level BEOL build-up structure **310** may be used to make D2D interconnects **316**, which may also utilize the aforementioned vias **312**. External chip pads **150** may then be formed, followed by application of (solder) bumps **140**.

[0056] FIG. 5 illustrates a back end of the line wiring sequence for contact with a top metal layer in accordance with embodiments. FIG. 5 is similar to FIG. 4 with one difference being that the via 312 contacts make contact with the top metal layer (e.g. M_D) pads 118. Thus, the vias may be shallower vias by comparison, and via pitch may be limited by die pad 118 pitch. In an embodiment, the pads 118 for D2D interconnects 316 may be of finer pitch than the external chip pads 150 for the chip 300 (e.g. for flip chip). This structure may also be beneficial for power delivery.

[0057] Referring now to FIG. 6 a back end of the line wiring sequence is illustrated for vias 116 and pads 118 built in the original die 110 in accordance with embodiments. In such an embodiment, the die 110 vias 116 and pads 118 may be fabricated while in the initial wafer format, after testing. Thus, after testing a thin oxide 114 can be formed over the illustrated top metal layer test pads 112. The die-level BEOL build-up structure 115 vias 116 and pads 118 are then formed after testing, followed by dicing of the known good dies 110. Then, the reconstituted wafer process is performed, and the reconstituted chip-level build-up structure 310 and intra-die interconnects 314 are formed, as well as D2D interconnects 316. In this instance, shallower reconstituted chip-level vias 312 may be required in the reconstituted chip-level BEOL build-up structure 310 to contact the die 110 metal. This may be a very fine pitch option, with die placement accuracy limited. If area is larger, reticle stitching can be performed. Lastly, external bumps 140 are applied. Some physical characteristics of the embodiment of FIG. 6 include finer pitch shallower via in the reconstituted chip-level BEOL process, and the die-level vias 116 and pads 118 are above the probe pads 112.

[0058] It is to be appreciated that while FIGS. 4-6 are described and illustrated separately, the via descriptions may be combined in some embodiments. Furthermore, while a single metal or interconnect layer is illustrated in the reconstituted chip-level BEOL build-up structure 310, it is understood multiple metal or interconnect layers may be formed, and may have different thicknesses (e.g. M_C , M_D , etc.). In some embodiments, the quality of service can be used to organize metal usage based on requirements such as latency, power, etc.

[0059] FIGS. 7A-7C illustrate a die-level BEOL build-up structure 115 processing sequence in accordance with embodiments. As shown in FIG. 7A the process sequence begins with a semiconductor substrate 111 (e.g. silicon wafer) including an active (device) layer including active devices 113, and die-level BEOL build-up structure 115 including very fine pitch metal layers (e.g. M_A), coarser pitch metal layers (e.g. M_B , M_C), and a top metal layer (e.g. M_D) which can be aluminum for example. In an embodiment, the die-level BEOL layers include damascene (e.g. single or dual damascene) interconnects. The top metal layer (e.g. M_D) may include test pads 112. In an embodiment, the lower metallization layers are fabricated using standard copper processing, while the upper metal layers (e.g. M_D , and optionally M_C) can be fabricated using aluminum processing.

[0060] Each individual die (still within the wafer) is then tested with a test probe, landing on the test pads 112 in the top metal layer. The wafer, and test pads 112, may then be cleaned, followed by application of an oxide layer 114. A thin oxide layer 114 may then be optionally formed on the top metal layer followed by singulation of dies 110 along

scribe lines as illustrated in FIG. 7C. At this stage, the dies 110 can be binned into known good die (KGD1). This process is repeated for a second wafer that will supply known good die (KGD2), and so forth for additional wafers '2 . . . n'.

[0061] A carrier is then provided, and groups of known good dies 110 are then mounted on the carrier substrate 205. For example, this may be oxide bonding. In an embodiment, this may include bonding of die 110 sets (e.g. KGD1, KGD2, etc.). The process flows may differ depending upon whether the dies 110 are mounted face up, or face down on the carrier substrate.

[0062] FIG. 8 is a process flow diagram of an aligned front die face-down processing sequence of a wafer reconstitution and die-stitching technique in accordance with embodiments. FIGS. 9A-9E are cross-section side view illustrations of the process flow illustrated in FIG. 8 with a front side reconstituted chip-level BEOL build-up structure in accordance with embodiments. FIGS. 9F-9K are cross-section side view illustrations of the process flow illustrated in FIG. 8 with a back side reconstituted chip-level BEOL build-up structure in accordance with embodiments. It is to be appreciated that the processing sequences of FIGS. 9A-9E and FIGS. 9F-9K are inclusive of different gap fill matrix materials (e.g. oxide, silicon, oxynitride, etc.). Additionally, several process variations are possible. In interests of clarity and conciseness the process sequences of FIG. 8, FIGS. 9A-9E and FIGS. 9F-9K as well as variations are described together.

[0063] As shown in FIGS. 9A and 9F, the processing sequence can begin at operation 810 with mounting a plurality of groups of die sets 110A, 110B, etc. (including at least two dies 110) face down (active side down) onto a carrier substrate 205. Each die 110 may have a height variation. The die thicknesses may be 5-100 μm (for easier handling). The dies 110 can be oxide bonded with the carrier substrate 205. For example, oxide layer 114 may be bonded with an oxide layer on the carrier substrate 205. Incoming dies may be cleaned separately (minimum test and scribe residue). The thicker die members of the die sets can then optionally be thinned by grinding, or CMP polishing at operation 815. This is illustrated in FIG. 9G, though may also be performed after FIG. 9A. This thickness reduction of the thicker die members can facilitate subsequent gap filling and reduces the die to die height variation. Likewise, all die members can be thinned to provide equal thicknesses and remove a step surface between die member thicknesses in the die sets.

[0064] In an embodiment, prior to known good die placement (or even die dicing), the die test pads 112 (e.g. aluminum pads from testing) may be repaired and cleaned. This may be followed by deposition of extra oxide layer 114, and optionally building of vias 116 and pads 118 as described in with regard to FIG. 6.

[0065] As shown in FIG. 9B and FIG. 9H, at operation 820 a gap fill 130 material is deposited on the carrier substrate 205 such that it laterally surrounds each of the plurality of groups of die sets. The gap fill 130 may then be planarized as needed, which may optionally expose the back sides of one or more die sets 110A, 110B, etc. In some embodiments the gap fill 130 material is an oxide. Where silicon is implemented (e.g. sputter, LPCVD, hot wire CVD, silicon ink, silicon paste, electro-deposition) this may allow for CTE matching with the dies 110. In such a silicon-silicon

system, better mechanical matching can be achieved. Additionally, thicker dies **110** may be potentially used compared to an oxide gap fill, in which deposition may take longer.

[0066] The process sequences may then vary depending upon whether a front side or back side reconstituted chip-level BEOL build-up structure is to be performed. In a front side approach, at operation **830** a second (back) carrier substrate **200** can then be bonded opposite the first (front) carrier substrate **205**, followed by removal of the first carrier substrate **205** at operation **840** and as illustrated in FIG. **9C**. At this point the die **110** faces (active side) are on the exposed side. Referring now to FIG. **9D**, the structure is flipped and at operation **850** a reconstituted chip-level BEOL build-up structure **310** is built on the plurality of groups of die sets and the gap fill **130** material. This is different from CoW sequences described because the reconstituted chip-level BEOL build-up structure **310** does not need to be hybrid bonded, and instead can be formed in a layer by layer processing sequence including polymers/metal or oxide/metal, for example. The individual reconstituted chip-level BEOL build-up structure routings can be tested, followed by dicing for chip singulation as shown in FIG. **9E**. The processing sequence illustrated in FIGS. **9A-9E** may allow for die **110** height variation since the active sides are facing out for the processing sequences.

[0067] In a back side D2D interconnect approach, at operation **835** through silicon vias (TSVs) **902** can then be formed in the plurality of groups of die sets, or revealed (e.g. pre-formed TSVs are revealed). At this point the die **110** faces (active side) are still facing down, and at operation **845** a reconstituted chip-level BEOL build-up structure **310** is built on the back sides of the plurality of groups of die sets, TSVs **902**, and the gap fill **130** material as illustrated in FIG. **9I**. The reconstituted chip-level BEOL build-up structure **310** may include the D2D interconnects **316**, on-chip (intra-chip) wiring **314**, and one or more dielectric layers as previously described. Thus, the back side reconstituted chip-level BEOL build-up structure **310** include the D2D connections through TSVs **902**. A second (back) carrier substrate **200** can then be bonded opposite the first (front) carrier substrate **205**, followed by removal of the first carrier substrate **205** at operation **855** and as illustrated in FIG. **9J**. At this point the die **110** faces (active side) are on the exposed side that can be used to connect to the package. Referring now to FIG. **9K**, an additional front side reconstituted chip-level BEOL build-up structure **910** can optionally be built on the plurality of groups of die sets and the gap fill **130** material, and more specifically on the die-level BEOL build-up structures **115**. This structure may be followed by singulation and removal of carrier substrate **200**, application of bumps **140**, additional WoW bonding, etc. The front side reconstituted chip-level BEOL build-up structure **910** may be substantially similar to reconstituted chip-level BEOL build-up structures **115**, **310** previously described and include the same features.

[0068] FIG. **10** is a process flow diagram of an aligned front die face-up processing sequence of a wafer reconstitution and die-stitching technique in accordance with embodiments. FIGS. **11A-11D** are cross-section side view illustrations of the process flow illustrated in FIG. **10** in accordance with embodiments. It is to be appreciated that the processing sequence of FIGS. **11A-11D** is inclusive of different gap fill matrix materials (e.g. oxide, silicon). Additionally, several process variations are possible. In interests

of clarity and conciseness the process sequences of FIG. **10** and FIGS. **11A-11D** as well as variations are described together.

[0069] As shown in FIG. **11A**, the processing sequence can begin at operation **1010** with mounting a plurality of groups of die sets (including at least two dies **110**) face up (active side up) onto a carrier substrate **200**. Each die **110** may have a small height variation. For example only, variation may be ± 1 μm , with thickness of each die being 5-20 μm . Thickness variation may be less than that of FIG. **9A**. The dies **110** can be oxide bonded with the carrier substrate **200**, for example. Incoming dies may be cleaned separately (minimum test and scribe residue). As shown in FIG. **11B** at operation **1020** a gap fill **130** material is deposited onto the carrier substrate **205** such that it laterally surrounds each of the plurality of groups of die sets. The gap fill **130** may then be planarized as needed. Referring now to FIG. **11C**, at operation **1030** a reconstituted chip-level BEOL build-up structure **310** is built on the plurality of groups of die sets **110A**, **110B**, etc. and the gap fill **130** material. This is different from CoW sequences described because the reconstituted chip-level BEOL build-up structure does not need to be hybrid bonded, and instead can be formed in a layer by layer processing sequence including polymers/metal or oxide/metal, for example. Formation of the reconstituted chip-level BEOL build-up structure **310** may include formation of vias **312**, which can extend through the gap fill **130** material. Since active sides are facing up, via **312** height to the dies **110** needs to be sufficient to contact the die-level BEOL build-up structures **115**. For example, this may be greater than die **110** height variation. After planarizing, vias **312** may be exposed (at least on one of the dies, perhaps not all if different thicknesses). The remainder of the reconstituted chip-level BEOL build-up structure **310** may then be formed. In some embodiments the gap fill **130** material is an oxide. Where silicon is implemented (e.g. sputter, CVD, PECVD, LPCVD, hot wire CVD, silicon ink, silicon paste, electro-deposition) this may allow for conformal, low temperature deposition and CTE matching with the dies as previously described.

[0070] The individual reconstituted chip-level BEOL routings can then be tested, followed by dicing for chip **300** singulation as shown in FIG. **11D**. The processing sequence illustrated in FIGS. **11A-11D** may be a less expensive processing sequence option. An additional processing sequence variation is also described and illustrated with regard to FIGS. **17A-17E** which may further reduce processing costs.

[0071] The wafer reconstitution and die-stitching techniques in accordance with embodiments may also provide particle sensitivity reduction compared to CoW hybrid bonding. FIG. **12A** is a schematic cross-sectional side view illustration showing a particle **1200** during wafer reconstitution phase and hybrid bonding of a CoW process. Planarity requirements can be strict (such as a root mean square (RMS) roughness of approximately 1-5 nm), and even small particles (e.g. with maximum particle size of 10 nm) can open a large number of pads **118**, **122**, with potential yield impact. Thus, particle size and planarity requirements are tightly linked, and needs a very clean environment for assembly, which can be expensive. As a corollary, a 10 nm particle size control may need a technology node cleanliness better than 20 nm, with implications to setup and operating costs. FIG. **12B** is a schematic top view illustration showing

particle sensitivity on a CoW hybrid bonding process. As shown, pad **118**, **122** connections between die **110** and interposer **120** may be coarser features (e.g. power, ground pads, etc.) compared to the finer pads **118**, **122** and features/wiring in the die-to-die interconnects **125**. As shown, particles **1200** can cause yield loss in any of these areas, and particle sensitivity is over 100% of the hybrid bond area, even though the fine features in the smaller area (e.g. 10% of overall).

[0072] FIG. 13A is a schematic cross-sectional side view illustration showing less particle **1200** sensitivity during wafer reconstitution phase of a wafer reconstitution and die-stitching technique process in accordance with an embodiment. FIG. 13B is a schematic cross-sectional side view illustration showing a particle **1200** during interconnection phase of a wafer reconstitution and die-stitching technique process in accordance with an embodiment. As shown in FIGS. 13A-13B, via **312** height over-etch can be used to compensate for defects (particles). Exemplary pad **118** pitch of approximately 10 μm , and D2D interconnect **316** pitch of approximately 1 μm may be much larger than the particle (e.g. approximately 100 nm). This is 10 \times larger than the CoW case. Thus, wafer reconstitution and die-stitching techniques in accordance with embodiments can reduce particle size sensitivity by selecting physical/process dimensions. This can lead to a more relaxed cleanliness and assembly options. As a corollary, a 100 nm particle size control needs a technology node cleanliness better than 200 nm (a very mature technology node). FIG. 13C is a schematic top view illustration showing particle **1200** effect on a wafer reconstitution and die-stitching technique process in accordance with an embodiment. Similar to FIG. 12B, pad **118** connections between the dies **110** and the reconstituted chip-level BEOL build-up structure **310** may be coarser features (e.g. power, ground pads, etc.) compared to the finer pad **118**, via **312** and features/wiring in the D2D interconnects **316**. As shown, particle sensitivity is largely limited to the fine pitch area (e.g. 10% overall), which can improve yield. Due to coarser feature sizes, the particles over the other die areas have much less impact on yield. Furthermore, by making the features sizes in the D2D interconnect **316** areas larger, fail probability can be further lowered.

[0073] The reconstituted chip-level BEOL build-up structure **310** interconnections used for die stitching may implement suitable conductive materials and BEOL processing techniques. In some embodiments, either copper wiring and/or aluminum wiring may be utilized when forming the reconstituted chip-level BEOL build-up structure **310** with the wafer reconstitution and die-stitching techniques. For example, aluminum wiring may be more amenable to a very mature BEOL manufacturing line that does not support a copper BEOL process. Some very mature process and manufacturing lines only support aluminum. Aluminum process may be sufficient for some applications, and cheaper than copper. In more traditional aluminum interconnections, aluminum wiring is combined with tungsten plugs for multi-layer fine pitch options (usually as lower metal layer close to silicon). Tungsten process adds expense, as does aluminum metal layer definition. Conversely, copper dual damascene process can be expensive due to the cost of barrier and cap layers to prevent copper diffusion. In an embodiment, the BEOL interconnections include aluminum dual damascene connections. Aluminum dual damascene may optionally include reflow for planarization and filling purposes,

which could exceed 450° C. In some embodiments with such an electro-deposited aluminum dual damascene embodiment, there is no tungsten via, and no reflow. This enables a fine metal pitch because of smoother topography.

[0074] FIGS. 14A-14C are schematic cross-sectional side view illustrations of an aluminum dual damascene process in accordance with an embodiment. As illustrated, in FIG. 14A the sequence can include a first dielectric layer **1402** and second dielectric layer **1406** separated by an etch stop layer **1404**. A via **1410** opening and trench **1412** opening may be formed using either a via first or via last approach. As shown in FIG. 14B, a bulk aluminum layer **1420** is deposited to fill the via **1410** opening and trench **1412** opening. This may be followed by a reflow process, and planarization resulting in the dual damascene interconnect **1422** as illustrated in FIG. 14C.

[0075] FIGS. 15A-15D are schematic cross-sectional side view illustrations of a gap fill deposition sequence in accordance with embodiments. In the particular sequence illustrated, the die **110** sets are mounted face down onto a carrier substrate **205** as previously described and illustrated with regard to FIG. 9A, however, embodiments are not so limited, and the gap fill deposition sequence may be performed with die **110** sets mounted face up as illustrated in FIG. 11A. A first conformal layer **131** may then be formed as illustrated in FIG. 15B. For example, this may be thin oxide, nitride, silicon layer etc. to provide good step coverage. In an embodiment, the first conformal layer **131** is formed using a higher quality, and slower deposition method such as high temperature CVD processes, which may result in epitaxial growth. A bulk layer **133** may then be deposited as illustrated in FIG. 15C. The bulk layer **133** may be formed using a process that results in a lower quality material (e.g. more defects), and at deposited at a higher rate. The gap fill **130** may then be planarized as illustrated in FIG. 15D, which may optionally expose the back sides of the dies **110**.

[0076] The gap fill **130** material may be formed of multiple layers and may include multiple layers of different materials in accordance with embodiments. While a first conformal layer **131** and bulk layer **133** are illustrated in FIG. 15D, the gap fill **130** may include multiple conformal layers, and other layer stacks. In an embodiment illustrated in FIG. 15E, growth properties of the gap fill **130** layers may result in an air gap **1500** between die **110** sets. For example, an air gap may contribute dielectric properties to the resultant chip structure.

[0077] Selection of appropriate gap fill **130** deposition technique may additionally consider aspect ratios of die height to gap between the die sets. In accordance with embodiments the gap between adjacent dies **110** in a die set is characterized by an aspect ratio of approximately 1 or higher such as 1-2, or even as high as 5, though higher aspect ratios are possible. For an exemplary aspect ratio of 5, the dies **110** may have a minimum die height of 10 μm , with gap of 2 μm . Yet, lower aspect ratios may be easier to fill, with reduced time requirements. In an embodiment illustrated in FIG. 15E, the die **110** sidewalls **199** may be tapered to facilitate gap fill.

[0078] FIGS. 16A-16D are schematic cross-sectional side view illustrations of a gap fill deposition sequence including silicon ink or paste deposition in accordance with embodiments. As illustrated, the sequence may begin similarly as with FIG. 15A with the optional deposition of a first conformal layer **131**. For example, this may be a PECVD

epitaxial deposition process of silicon. Alternatively, an oxide or nitride layer may be deposited. This first conformal layer **131** forms a high quality gap fill seal. Referring to FIGS. **16B-16C**, a bulk layer **133** of silicon ink or paste can be deposited followed by reflow. For example, reflow may occur at temperature of less than 350° C. The low reflow temperature may be the result of the size and shape of silicon nanocrystals with the ink or paste. For example, the silicon nanocrystals may have a maximum width of less than 4 nm. The gap fill **130** may then be planarized as illustrated in FIG. **16D**, which may optionally expose the back sides of the dies **110**.

[**0079**] Silicon ink or pastes may additionally be used for mechanical die leveling in accordance with embodiments. FIGS. **17A-17E** are schematic cross-sectional side view illustration of an aligned front die face-up processing sequence of a wafer reconstitution and die-stitching technique with mechanical leveling in accordance with embodiments. In particular, the sequence illustrated in FIGS. **17A-17E** is a modification to the face up sequence illustrated in FIGS. **11A-11C** in which a moldable layer is deposited which is used to flatten the top surface topography of the dies **110** prior to formation of the gap fill **130** material. This allowed for the formation of a reconstituted chip-level BEOL build-up structure **310** where via **312** height does not need to be different for dies **110** of different height. This sequence also allows for a single carrier substrate processing sequence, as opposed to the face down processing sequence of FIGS. **9A-9E** that utilizes two carrier substrates.

[**0080**] As illustrated, the sequence may begin with the deposition of a moldable layer **1710**. For example, this may be a silicon ink or paste, which may behave as a silicon solder. The die **110** sets are then placed onto the moldable layer **1710** as shown in FIG. **17B**, followed by the flattening with a plane surface **1720**. As shown in FIG. **17C**, the top surfaces of the dies **110** are now level, and the bottom surfaces sink into the moldable layer **1710**. Heat may then be applied to set the moldable layer **1710** resulting in the die being attached to the carrier substrate by moldable layer **1710**. This may then be followed by formation of the gap fill **130** material, followed by a reconstituted chip-level BEOL build-up structure **310** as illustrated in FIGS. **17D-17E**.

[**0081**] Until this point deposition of the gap fill **130** material and aspect ratio between die **110** sets has been described without regard to carrier substrate (wafer) edges, or scribing of die sets. In an embodiment illustrated in FIG. **18A** a dummy structure **1810** is formed between die sets to maintain the aspect ratios of the gaps around the die sets **110A**, **110B**, etc. For example, such a configuration may be utilized when scribe lines (illustrated by dashed lines) are wider than the gaps between the dies **110** within a die set **110A**, **110B**, etc. FIG. **18B** is an illustration of dummy structures **1810** formed around the carrier substrate (wafer) edges so that gap filling, and aspect ratios are maintained for the dies **110** near the edges.

[**0082**] Referring now to FIG. **19**, a high-level flow chart of a wafer reconstitution flow is provided in accordance with embodiments. As shown, at operation **1910** a plurality of wafers (1 . . . n) are processed to determine known good die KGD1 . . . KGDn, with acceptable dies **110** indicated with check-marks and defective dies **110** indicated with x-marks. The known good die sets are then reconstituted onto a wafer (e.g. FIGS. **9A-9C**; **11A-11B**; **17A-17D**) at operation **1920**. The known good dies may then be polished, cleaned and

made “prime” at operation **1930**. A mature fab process may be utilized for this sequence, with no (or few) new line required. The fab sequence may also be re-formatted to a 200 mm or 300 mm wafer line, or a larger panel line such as 500x500 mm.

[**0083**] The known good reconstituted wafer (KGRW) can then be re-introduced into the fab for reconstituted chip-level BEOL processing and D2D interconnection (e.g. FIGS. **9D**; **11C**; **17E**) at operation **1940**. This is followed by testing, dicing and final packaging at operation **1950**.

[**0084**] Alternatively, rather than testing and dicing at this point, the KGRWs with a reconstituted chip-level BEOL build-up structures can be bonded for 3D wafer on wafer (WoW) packaging. In the illustrated case KGRW1 and KGRWn are bonded at operation **1945** with a wafer on wafer bond, followed by dicing and final packaging at operation **1955** for a 3D packaging solution.

[**0085**] FIG. **20** is a flow chart comparing yield considerations of wafer on wafer, chip on wafer, and a hybrid process flow of wafer reconstitution and die-stitching technique in accordance with embodiments. As illustrated, the x-marks indicate defective dies, while check-marks indicate acceptable dies after testing. As shown, in the WoW technique, active dies are wasted. Both the bottom and top die have to yield. Process cost is wasted on non-yielding die. For a CoW technique active die are saved. Process cost is wasted on non-yielding portions of the base wafer. In a hybrid approach which uses a KGD1 bottom wafer and KDG2 top wafer both base and top wafer yields are improved. Process cost is lower as both top and bottom die have high yielding dies. Thus, the reconstituted wafers in accordance with embodiments can be used in wafer on wafer techniques (surface, alignment, TSV, bonding preparation) for the fabrication of 3D reconstituted chips.

[**0086**] In utilizing the various aspects of the embodiments, it would become apparent to one skilled in the art that combinations or variations of the above embodiments are possible for forming a chip with a wafer reconstitution and die-stitching technique. Although the embodiments have been described in language specific to structural features and/or methodological acts, it is to be understood that the appended claims are not necessarily limited to the specific features or acts described. The specific features and acts disclosed are instead to be understood as embodiments of the claims useful for illustration.

What is claimed is:

1. A semiconductor structure comprising:
 - a wiring layer;
 - a die set on the wiring layer; and
 - a silicon containing gap fill material on the wiring layer and laterally surrounding the die set.
2. The semiconductor structure of claim 1, wherein the wiring layer is within an interposer.
3. The semiconductor structure of claim 1, wherein the wiring layer is within a chip-level back end of the line (BEOL) build-up structure.
4. The semiconductor structure of claim 1, wherein:
 - the die set includes a first die and a second die; and
 - the first die includes a first die-level BEOL build-up structure, and the second die includes a second die-level BEOL build-up structure; and
 - the first and second die-level BEOL build-up structures each include damascene interconnects.

5. The semiconductor structure of claim 1, wherein the die set includes a pair of dies, and further comprising a planarized surface along the silicon containing gap fill material and back sides of the pair of dies.

6. The semiconductor structure of claim 1, wherein the silicon containing gap fill material includes a silicon matrix.

7. The semiconductor structure of claim 1, wherein the silicon containing gap fill material includes silicon crystals.

8. The semiconductor structure of claim 7, wherein:
the silicon containing gap fill material comprises a conformal layer and a bulk layer;

the conformal layer is formed on the die set and underneath the bulk layer; and

the bulk layer comprises the silicon crystals.

9. The semiconductor structure of claim 8, wherein the conformal layer is a higher quality layer than the bulk layer.

10. The semiconductor structure of claim 9, wherein the conformal layer comprises and oxide, nitride, or silicon.

11. The semiconductor structure of claim 8, wherein the die set includes a pair of dies, and further comprising a planarized surface along the conformal layer, the bulk layer, and back sides of the pair of dies.

12. The semiconductor structure of claim 1, wherein the die set includes a first die and a second die, each having a thickness of at least 20 μm .

13. The semiconductor structure of claim 1, wherein the silicon containing gap fill material does not cover back sides of the first die and the second die.

14. The semiconductor structure of claim 1, wherein the die set includes a first die and a second die, each having a thickness of less than 20 μm .

15. The semiconductor structure of claim 14, further comprising a silicon containing layer spanning over the silicon containing gap fill material and a back side of the first die.

16. The semiconductor structure of claim 15, wherein a second die is thicker than the first die.

17. The semiconductor structure of claim 15, further comprising a carrier substrate bonded to the silicon containing layer opposite the die set.

18. The semiconductor structure of claim 1, wherein the die set includes a first die and a second die, and further comprising a carrier substrate bonded to back sides of the first die and the second die.

19. The semiconductor structure of claim 18, wherein the carrier substrate is bonded to the back sides of the first die and the second die with a moldable layer.

20. The semiconductor structure of claim 19, wherein the moldable layer comprises silicon.

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